

# Quad Parametric Measurement Unit With Integrated 16-Bit Level Setting DACs

**Preliminary Technical Data** 

# AD5522

### FEATURES

**Ouad Parametric Measurement Unit** FV, FI, FN, MV, MI Functions 4 Programmable Current Ranges (Internal R<sub>SENSE</sub>) 5uA, 20uA, 200uA and 2mA 1 Programmable Current Range up to 64mA (external R<sub>SENSE</sub>) 22.5 V FV Range with Asymmetrical Operation **Integrated 16-Bit DACs Provide Programmable Levels Offset and Gain Correction on Chip** Low Capacitance Outputs Suited to Relay Less Systems **On-chip Comparators Per Channel** FI Voltage Clamps & FV Current Clamps **Guard Drive Amplifier** System PMU connections **Programmable Temperature Shutdown Feature** SPI/Microwire/DSP & LVDS Compatible Interfaces Compact 80 lead TQFP Package with Exposed Pad (Top Or Bottom)

### **APPLICATIONS**

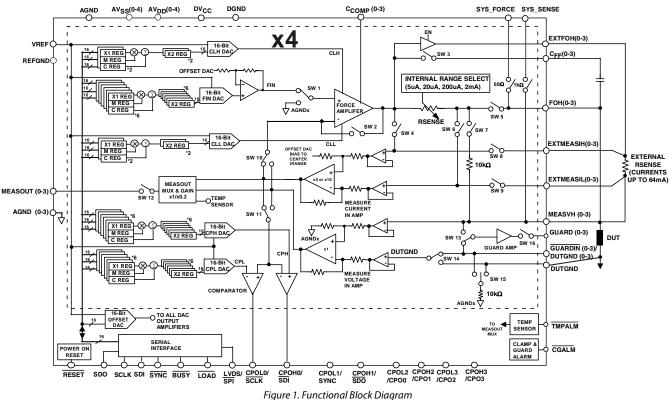
Automatic Test Equipment (ATE) per pin Parametric Measurement Unit Continuity & Leakage Testing Device Power Supply Instrumentation SMU (Source Measure Unit)

### **Precision Measurement**

### **PRODUCT OVERVIEW**

The AD5522 is a high performance, highly integrated parametric measurement unit consisting of four independent channels. Each PPMU channel includes five, 16-bit, voltage out DACs setting the programmable inputs levels for the force voltage input, clamp and comparator inputs (high and low). Five programmable force and measure current ranges are available ranging from  $5\mu$ A to 64mA. Four of these ranges use on chip sense resistors, while a high current range up to 64mA is available per channel using off chip sense resistors. Currents in excess of 64mA require an external amplifier. Low capacitance DUT connections (FOH, EXT FOH) ensure the device is suited to relay less test systems. The PMU functions are controlled via a simple three wire serial interface compatible with SPI/QSPI/Microwire and DSP interface standards. Interface clocks of 50MHz allow fast updating of modes. LVDS (Low Voltage Differential Signaling) interface protocol at

100MHz is also supported. Comparator outputs are provided per channel for device go no-go testing and characterization. Control registers provide easy way of changing force or measure conditions, DAC levels and selected current ranges. SDO (serial data out) allows the user to readback information for diagnostic purposes.



#### Rev.PrM

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Readback of Comparator Status Register Readback of Alarm Status Register Readback of DAC Register Power On Default Setting up the device on power on	<ol> <li>39</li> <li>40</li> <li>40</li> <li>41</li> <li>42</li> <li>42</li> </ol>
Readback of Comparator Status Register Readback of Alarm Status Register Readback of DAC Register Power On Default Setting up the device on power on Changing Modes	<ol> <li>39</li> <li>40</li> <li>40</li> <li>41</li> <li>42</li> <li>42</li> <li>43</li> </ol>
Readback of Comparator Status Register Readback of Alarm Status Register Readback of DAC Register Power On Default Setting up the device on power on Changing Modes Required external components	<ol> <li>39</li> <li>40</li> <li>40</li> <li>41</li> <li>42</li> <li>42</li> <li>43</li> <li>45</li> </ol>
Readback of Comparator Status Register Readback of Alarm Status Register Readback of DAC Register Power On Default Setting up the device on power on Changing Modes Required external components Typical Application for the AD5522	<ol> <li>39</li> <li>40</li> <li>40</li> <li>41</li> <li>42</li> <li>42</li> <li>43</li> <li>45</li> <li>46</li> </ol>

### **REVISION HISTORY**

Rev PrM, 12th March - Update to specification pages, addition of typical plots, general update of all sections of datasheet. Update of AD5522 models. .

# **Preliminary Technical Data**

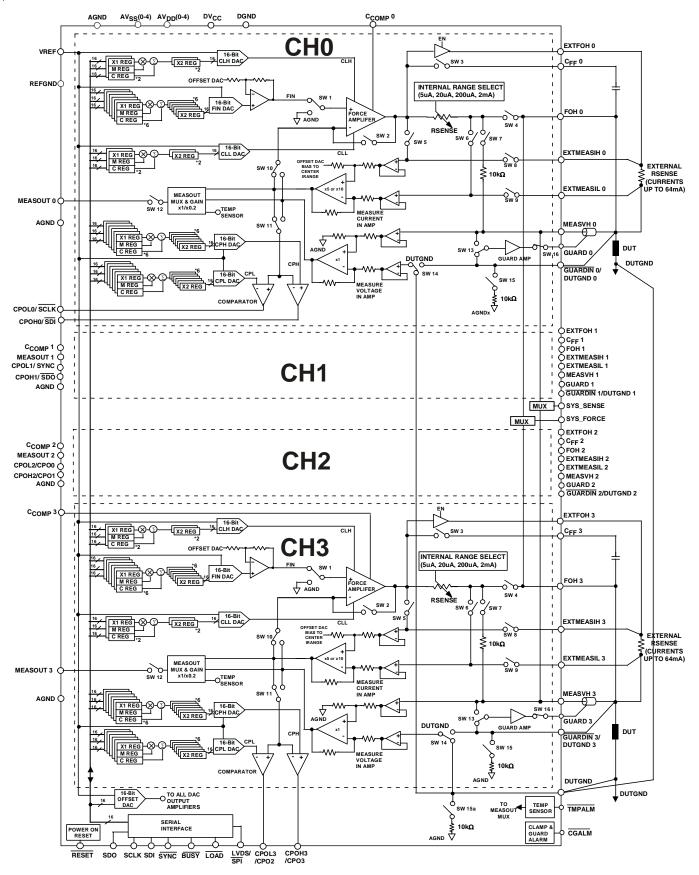


Figure 2. Detailed Block Diagram

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# SPECIFICATIONS

Table 1.  $AV_{DD} \ge 10V$ ,  $AV_{SS} \le -5V$ ,  $|AV_{DD} - AV_{SS}| \ge 20V$  and  $\le 33V$ ,  $DV_{CC} = 2.3V$  to 5.25V,  $V_{REF}=5V$ , Gain (m), Offset (c) and DAC Offset registers at default values ( $T_J = +25$  to  $+90^{\circ}C$ , max specs unless otherwise noted.)

Parameter	Min	Typ <sup>1</sup>	Max	Units	Test Conditions/Comments	
FORCE VOLTAGE						
FOH Output Voltage Range	AV <sub>ss</sub> +4		AV <sub>DD</sub> -4	V	All current ranges from FOH at full scale current. Includes ±1V dropped across sense resistor	
EXTFOH Output Voltage Range	AV <sub>ss</sub> +3		AV <sub>DD</sub> -3	V	External high current range at full scale current. Does not include $\pm 1V$ dropped across sense resistor	
Output Voltage Span			22.5	V		
Offset Error	-100		100	mV	Measured at Midscale Code, 0V. Prior to calibration.	
Offset Error Tempco <sup>2</sup>		±100		μV/°C		
Gain Error	-0.5		0.5	%	Prior to calibration.	
Gain Error Tempco <sup>2</sup>		±10		ppm/°C		
Linearity Error	-0.02		0.02	% FSR	$FSR = Fullscale Range. \pm 10 V range, Gain and offset errors calibrated out.$	
Short Circuit Current Limit <sup>2</sup>	-120		120	mA	On 64mA range.	
	-10		10	mA	In all other ranges.	
MEASURE CURRENT					MEASURE = (IDUT X RSENSE x GAIN)	
Offset Error	-1		1	%	V(Rsense)= $\pm 1V$ , Measured with zero current flowing.	
Offset Error Tempco <sup>2</sup>		±10		μV/°C		
Gain Error	-1	25	1	%	Instrumentation Amp Gain = 5 or 10	
Gain Error Tempco <sup>2</sup> Linearity Error	-0.01	25	0.01	ppm/°C % FSCR	Offset and Gain errors calibrated out	
Output Voltage Span <sup>2</sup>	-0.01		22.5	V V	Onset and Gaineriors calibrated out	
CM Error	-0.005		0.005	v %FSVR/V	% of FS Change at measure output per V change in DUT voltage	
Measure Current Ranges		±5		μA	Set using internal sense resistor	
j		±20		μA	Set using internal sense resistor	
		±200		μA	Set using internal sense resistor	
		±2		mA	Set using internal sense resistor	
			Up to ±64	mA	Set using external sense resistor, internal amplifier can drive to 64mA	
FORCE CURRENT						
Voltage Compliance, FOH	AV <sub>ss</sub> +4		AV <sub>DD</sub> -4	V		
Voltage Compliance, EXTFOH	AV <sub>SS</sub> +3		AV <sub>DD</sub> -3	V		
Offset Error	-2		2	%FSCR	Measured at Midscale Code, 0V. Prior to calibration.	
Offset Error Tempco <sup>2</sup>		±10		ppm FS/ ℃		
Gain Error	-0.5		0.5	%	Prior to calibration.	
Gain Error Tempco <sup>2</sup>		±25		ppm/°C		
Linearity Error	-0.02		0.02	% FSCR		
CM Error	-0.005		0.005	%FSCR/V	% of FS Change at measure output per V change in DUT voltage	
Force Current Ranges		±5		μΑ	Set using internal sense resistor, 200k $\Omega$	
		±20		μΑ	Set using internal sense resistor, 50k $\Omega$	
		±200		μΑ	Set using internal sense resistor, $5k\Omega$	
		±2		mA	Set using internal sense resistor, $500\Omega$	
			Up to ±64	mA	Set using external sense resistor, internal amplifier can drive to 64mA	

MEASURE VOLTAGE					
Measure Voltage Range			AV <sub>DD</sub> -4	v	
measure voltage hange	AV <sub>ss</sub> +4			v	
Offset Error	-10		10	mV	GAIN = 1, measured at 0V
Offset Error	-40		40	mV	GAIN = 1, measured at 0V GAIN = 0.2, measured at 0V
Offset Error Tempco <sup>2</sup>	-40	±10	40	μV/°C	GAIN – 0.2, measured at 0V
Gain Error	-0.5	±10	0.5	μν/ C % FSR	Gain = 1
Gain Error	-0.5		0.5	% FSR	Gain = 0.2
	-0.5	±10	0.5	ppm/°C	Gain = 0.2
Gain Error Tempco <sup>2</sup> Linearity Error	-0.01	±10	0.01	% FSR	
COMPARATOR	0.01		0.01	701 511	
Comparator Span			22.5	v	
Offset Error	-10	1	10	mV	
Propagation delay <sup>2</sup>	-10	0.25	10	μs	
VOLTAGE CLAMPS		0.25		μ	
Clamp Span			22.5	v	
Positive Clamp Accuracy			150	mV	
Negative Clamp Accuracy	-150		001	mV	
Recovery Time <sup>2</sup>	-150	0.5	1.5	μs	
Activation Time <sup>2</sup>		1.5	3	•	
		L.1	5	μs	
CORRENT CLAMPS	Drog/d		Programmed		
Clamp Accuracy	Prog'd Clamp		Clamp value	% of FSC	Clamp current scales with selected range
clump //ccurucy	value		+15	range	clump current scales with selected range
Recovery Time <sup>2</sup>		0.5	1.5	μs	
Activation Time <sup>2</sup>		1.5	3	μs	
FOH, EXTFOH, EXTMEASIL,					
EXTMEASIH, CFF					
Pin Capacitance <sup>2</sup>		10		pF	
Leakage Current	-3		3	nA	On or off switch leakage
Leakage Current Tempco <sup>2</sup>		±0.1		nA/°C	
MEASVH					
Pin Capacitance <sup>2</sup>		3		pF	
Leakage/Bias Current	-3		3	nA	
Leakage Current Tempco <sup>2</sup>		±0.1		nA/°C	
SYS_SENSE					SYS_Sense Connected, Force Amplifier Inhibited
Pin Capacitance <sup>2</sup>		3		pF	
SYS_SENSE Impedance		1	1.3	kΩ	
Leakage Current	-3		3	nA	
Leakage Current Tempco <sup>2</sup>		±0.1		nA/°C	
SYS_FORCE					SYS_Force Connected, Force Amplifier Inhibited
Pin Capacitance <sup>2</sup>		6		pF	
SYS_FORCE Impedance		60	80	Ω	
Leakage Current	-3		3	nA	
Leakage Current Tempco <sup>2</sup>		±0.1		nA/°C	
COMBINED LEAKAGE at DUT					Includes FOH, MEASVH, SYS_SENSE, SYS_FORCE, EXTMEASIL
Leakage Current	-15		15	nA	
Leakage Current		1	-		
÷		±0.5		nA/°C tvp	
Leakage Current Tempco <sup>2</sup>		±0.5		nA/°C typ	
-	-500	±0.5	500	nA/°C typ mV	

MEASURE OUTPUT (MEASOUT)					With respect to AGND
Measure Output Voltage Span			22.5	v	Software Programmable output range
Measure Pin output Impedance			100	Ω	
Output leakage current	-3		3	nA	With SW12 off
Output Capacitance <sup>2</sup>	5		15	pF	
Max Load Capacitance <sup>2</sup>			1	μF	
Output Current drive <sup>2</sup>		2	•	mA	
Short Circuit Current <sup>2</sup>	-10	-	10	mA	
MEASOUT Slew Rate <sup>2</sup>	10	2	10	V/µs	
MEASOUT enable time <sup>2</sup>		150	320	ns	Closing SW12, Measured from BUSY rising edge.
MEASOUT disable time <sup>2</sup>		400	1100		Opening SW12, Measured from BUSY rising edge.
			1100	ns	
MEASOUT MI to MV switching time <sup>2</sup>		200		ns	Measured from BUSY rising edge.
GUARD OUTPUT			22.5	N/	
Guard Output Voltage Span	10		22.5	V	
Guard Output Offset	-10		10	mV	
Short Circuit Current <sup>2</sup>	-10		10	mA	
Max Load Capacitance <sup>2</sup>			1000	nF	
Guard Output Impedance		100		Ω	
Slew Rate <sup>2</sup>		5		V/µs	$C_{LOAD} = 10 \text{ pf}$
Alarm Activation Time <sup>2</sup>		200		μs	Alarm delayed to eliminate false alarms.
FORCE AMPLIFIER					
Slew Rate <sup>2</sup>		0.4		V/us	Ccomp=100pF, Cff=220pF, Cload=200pF
Gain Bandwidth <sup>2</sup>		1.3		MHz	Ccomp=100pF, Cff=220pF, Cload=200pF
Max stable load Capacitance <sup>2</sup>			10,000	pF	$C_{COMP} = 100 pF.$ Larger Load cap requires larger $C_{COMP}$
			100	nF	$C_{COMP} = 1$ nF. Larger Load cap requires larger $C_{COMP}$
FV SETTLING TIME TO 0.05% OF FS					Mid scale to full scale change, Measured from /SYNC rising edge, Clamps ON
64mA Range <sup>2</sup>		17	40	μs	Ccomp=100pF, Cff=220pF, Cload=200pF
2mA range <sup>2</sup>		17	40	μs	Ccomp=100pF, Cff=220pF, Cload=200pF
200µA range <sup>2</sup>		32	80	μs	Ccomp=100pF, Cff=220pF, Cload=200pF
20µA range <sup>2</sup>		TBD	80	μs	Ccomp=100pF, Cff=220pF, Cload=200pF
5µA range <sup>2</sup>		TBD	300	μs	Ccomp=100pF, Cff=220pF, Cload=200pF
MI SETTLING TIME TO 0.05% OF FS					Mid scale to full scale change, Measured from /SYNC rising edge, Clamps ON
64mA Range <sup>2</sup>		17	40	μs	Ccomp=100pF, Cff=220pF, Cload=200pF
2mA range <sup>2</sup>		18	40	μs	Ccomp=100pF, Cff=220pF, Cload=200pF
$200\mu$ A range <sup>2</sup>		40	80	μs	Ccomp=100pF, Cff=220pF, Cload=200pF
20μA range <sup>2</sup>		TBD	TBD	μs	Ccomp=100pF, Cff=220pF, Cload=200pF
5µA range <sup>2</sup>		TBD	TBD	μs	Ccomp=100pF, Cff=220pF, Cload=200pF
FI SETTLING TIME TO 0.05% OF FS				1	Mid scale to full scale change, Measured from /SYNC
FI JET I LING TIME I U U.UJ% UF FS					rising edge, Clamps ON
64mA Range <sup>2</sup>		18	55	μs	Ccomp=100pF, Cload=200pF
2mA range <sup>2</sup>		22	85	μs	Ccomp=100pF, Cload=200pF
200µA range <sup>2</sup>		45	120	μs	Ccomp=100pF, Cload=200pF
20µA range <sup>2</sup>		1000	TBD	μs	Ccomp=100pF, Cload=200pF
5µA range <sup>2</sup>		2300	4000	μs	Ccomp=100pF, Cload=200pF
MV SETTLING TIME TO .05% OF FS					Mid scale to full scale change, Measured from /SYNC rising edge, Clamps ON
64mA Range <sup>2</sup>		20	65	μs	Ccomp=100pF, Cload=200pF
2mA range <sup>2</sup>		21	85	μs	Ccomp=100pF, Cload=200pF
200µA range <sup>2</sup>		50	120	μs	Ccomp=100pF, Cload=200pF
20µA range <sup>2</sup>		1000	TBD	μs	Ccomp=100pF, Cload=200pF
5µA range <sup>2</sup>		2300	4000	μs	Ccomp=100pF, Cload=200pF

# **Preliminary Technical Data**

AD5522
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DAC SPECIFICATIONS					
Resolution			16	Bits	
Voltage Output Span <sup>2</sup>			22.5	V	$V_{REF}$ =5V, within a range of -16.25 to 22.5V
Differential Nonlinearity <sup>2</sup>	-1		1	LSB	Guaranteed monotonic by design over temperature.
COMPARATOR DAC DYNAMIC SPECIFICATIONS					
Output Voltage Settling Time <sup>2</sup>			1.5	μs	500mV change to $\pm \frac{1}{2}$ LSB.
Slew Rate <sup>2</sup>		5.5		V/µs	
Digital-to-Analog Glitch Energy <sup>2</sup>		20		nV-s	
Glitch Impulse Peak Amplitude <sup>2</sup>		10		mV	
REFERENCE INPUT					
V <sub>REF</sub> DC Input Impedance	1			MΩ	Typically 100 MΩ.
V <sub>REF</sub> Input Current	-10		10	μΑ	Per input. Typically ±30 nA.
V <sub>REF</sub> Range	2		5	V	
DIE TEMPERATURE SENSOR					
Accuracy		±7		°C	
Output Voltage at 25°C		1.5		V	
Output Scale Factor		5		mV/°C	
Output Voltage Range	0		3	V	
INTERACTION & CROSSTALK					
Crosstalk (VM) <sup>2</sup>	-0.01		0.01	% FSR	All channels in FIMV mode, measure the voltage for one channel in the highest current force range, once when all three other channels are at FI = 0mA and once when they are at 2mA
Crosstalk (MI) <sup>2</sup>	-0.01		0.01	% FSR	All channels in FVMI mode, measure the current for one channel in the lowest current measure range, once when all three other channels are at FV = -10V and once when they are at +10V
Crosstalk within a channel <sup>2</sup>			0.5	mV	All channels in FVMI mode, one channel at midscale, measure the current for one channel in the lowest current range, for a change in comparator or clamp DAC levels for that PMU.
Shorted DUT Crosstalk <sup>2</sup>		TBD	TBD		S/C applied to one PMU channel, measure effect on other channels.
SPI INTERFACE LOGIC					
LOGIC INPUTS					
V⊮, Input High Voltage	1.7/2.0			V	(2.3 to 2.7)/(2.7 to 5.25V) Jedec Compliant Input Levels
V <sub>IL</sub> , Input Low Voltage			0.7/0.8	V	(2.3 to 2.7)/(2.7 to 5.25V) Jedec Compliant Input Levels
I <sub>INH</sub> , I <sub>INL</sub> , Input Current	-1		1	μΑ	
C <sub>IN</sub> , Input Capacitance <sup>2</sup>			10	pF	
CMOS LOGIC OUTPUTS					SDO, CPOX
V <sub>OH</sub> , Output High Voltage	DV <sub>CC</sub> – 0.4			V	
V <sub>OL</sub> , Output Low Voltage			0.4	V	$I_{OL} = 500 \mu\text{A}$
Tristate leakage current	-1		1	μΑ	
Output Capacitance <sup>2</sup>			10	pF	
OPEN DRAIN LOGIC OUTPUTS					BUSY, TMPALM, CGALM
Vol, Output Low Voltage			0.4	V	$I_{OL} = 500 \ \mu\text{A}, \ C_L = 50 pF, \ R_{PULLUP} = 1 k\Omega$
Output Capacitance <sup>2</sup>			10	pF	
LVDS INTERFACE LOGIC					
LOGIC INPUTS – Reduced Range Link					
Input Voltage Range	875		1575	mV	
Input Differential Threshold	-100		100	mV	
External Termination Resistance	80	100	120	Ω	
Differential Input Voltage	100			mV	
LOGIC OUTPUTS – Reduced Range Link					
Output Offset Voltage		1200		mV	
Output Differential Voltage		400		mV	

NOISE PERFORMANCE					
NSD of Measure Voltage In-Amp		290		nV/√Hz	@ 1kHz, measured at MEASOUT
NSD of Measure Current In-Amp		290		nV/√Hz	@ 1kHz, measured at MEASOUT
NSD of Force Amplifier		300		nV/√Hz	@ 1kHz, measured at FOH
POWER SUPPLIES					
AV <sub>DD</sub>	10		28	V	$ AV_{DD} - AV_{SS}  \le 33V$
AV <sub>ss</sub>	-5		-23	V	
DVcc	2.3		5.25	V	
Al <sub>DD</sub>			25	mA	Internal ranges (5µA to 2mA), Excluding Load Conditions
Alss			-25	mA	Internal ranges (5µA to 2mA), Excluding Load Conditions
Al <sub>DD</sub>			35	mA	External range, Excluding Load Conditions
Alss			-35	mA	External range, Excluding Load Conditions
Dlcc			3	mA	
Max Power Dissipation <sup>2</sup>			7	W	
Power Supply Sensitivity <sup>2</sup>					From DC to 1kHz
ΔForced Voltage/ΔAV <sub>DD</sub>		-75		dB	
ΔForced Voltage/ΔAV <sub>ss</sub>		-75		dB	
$\Delta$ Measured Current/ $\Delta$ AV <sub>DD</sub>		-75		dB	
$\Delta$ Measured Current/ $\Delta$ AV <sub>ss</sub>		-75		dB	
$\Delta$ Forced Current/ $\Delta$ AV <sub>DD</sub>		-75		dB	
ΔForced Current/ΔAV <sub>ss</sub>		-75		dB	
$\Delta$ Measured Voltage/ $\Delta$ AV <sub>DD</sub>		-75		dB	
$\Delta$ Measured Voltage/ $\Delta$ AV <sub>ss</sub>		-75		dB	
$\Delta$ Forced Voltage/ $\Delta$ DV <sub>cc</sub>		-90		dB	
$\Delta$ Measured Current/ $\Delta$ DV <sub>cc</sub>		-90		dB	
$\Delta$ Forced Voltage/ $\Delta$ DV <sub>cc</sub>		-90		dB	
$\Delta$ Measured Current/ $\Delta$ DV <sub>cc</sub>		-90		dB	

 $^1$  Typical specifications are at 25°C and nominal supply, ±15.25V, unless otherwise noted.  $^2$  Guaranteed by design and characterization, not production tested.

FV = Force Voltage, FI = Force Current, MV = Measure Voltage, MI = Measure Current FSR = Full Scale Range, FSCR = Full Scale Current Range, FS = Full Scale. Specifications subject to change without notice.

### **TABLE 2. TIMING CHARACTERISTICS**

 $AV_{DD} \ge 10V$ ,  $AV_{SS} \le -5V$ ,  $|AV_{DD} - AV_{SS}| \ge 20V$  and  $\le 33V$ ,  $DV_{CC} = 2.3V$  to 5.25V,  $V_{REF} = 5V$ 

 $(T_J = +25 \text{ to } +90^{\circ}\text{C}, \text{ max specs unless otherwise noted.})$ 

SPI INTERFACE (Figure 5 and Figure 6)							
Parameter <sup>1, 2, 3</sup>	Limit at TMIN, TMAX	Unit	Description				
	595	ns min	Single channel write time				
t1	20	ns min	SCLK Cycle Time.				
t <sub>2</sub>	8	ns min	SCLK High Time.				
t <sub>3</sub>	8	ns min	SCLK Low Time.				
t4	10	ns min	SYNC Falling Edge to SCLK Falling Edge Setup Time.				
t <sub>5</sub>	15	ns min	Minimum SYNC High Time.				
t <sub>6</sub>	5	ns min	29th SCLK Falling Edge to SYNC Rising Edge.				
t <sub>7</sub>	5	ns min	Data Setup Time.				
t <sub>8</sub>	4.5	ns min	Data Hold Time.				
t9 <sup>3</sup>	30	ns max	SYNC Rising Edge to BUSY Falling Edge.				
t <sub>10</sub>			BUSY Pulse Width Low				
1 DAC X1	1.25	µs max	BUSY Pulse Width Low				
2 DAC X1	1.75	µs max	BUSY Pulse Width Low				
3 DAC X1	2.25	µs max	BUSY Pulse Width Low				
4 DAC X1	2.75	µs max	BUSY Pulse Width Low				
Other Regs	270	ns max	BUSY Pulse Width Low, System Control Register/PMU Register/M or C Registers				
t <sub>11</sub>	20	ns min	29 <sup>th</sup> SLCK Falling EDGE to LOAD Falling Edge				
t <sub>12</sub>	20	ns min	LOAD pulse width low				
t <sub>13</sub>	150	ns min	BUSY rising edge to FOH Output Response time				
t <sub>14</sub>	0	ns min	BUSY rising edge to LOAD falling edge				
t15	100	ns max	LOAD rising edge to FOH Output Response time				
t <sub>16</sub>	10	ns min	RESET Pulse Width Low.				
t <sub>17</sub>	300	µs max	RESET Time Indicated by BUSY Low.				
t <sub>18</sub>	100	ns min	Minimum SYNC High Time in Readback Mode.				
t <sub>19</sub> <sup>4, 5</sup>	25	ns max	$DV_{CC} = 5V$ to 5.25V, SCLK Rising Edge to SDO Valid.				
	45	ns max	DV <sub>cc</sub> = 3V to 3.7V, SCLK Rising Edge to SDO Valid				
	60	ns max	DV <sub>cc</sub> = 2.3V to 3V, SCLK Rising Edge to SDO Valid				
LVDS INTERFAC	E (Figure 7)						
Parameter <sup>1, 2, 3</sup>	Limit at TMIN, TMAX	Unit	Description				
t1	10	ns min	SCLK Cycle Time.				
t <sub>2</sub>	4	ns min	SCLK Pulse Width High and Low Time.				
t <sub>3</sub>	2	ns min	SYNC to SCLK Setup Time.				
<b>t</b> 4	2	ns min	Data Setup Time.				
t5	2	ns min	Data Hold Time.				
t <sub>6</sub>	2	ns min	SCLK to SYNC Hold Time.				
t <sub>7</sub>	TBD	ns min	SCLK Rising Edge to SDO Valid.				
t <sub>8</sub>	TBD sign and characterization, not pro	ns min	SYNC high time				

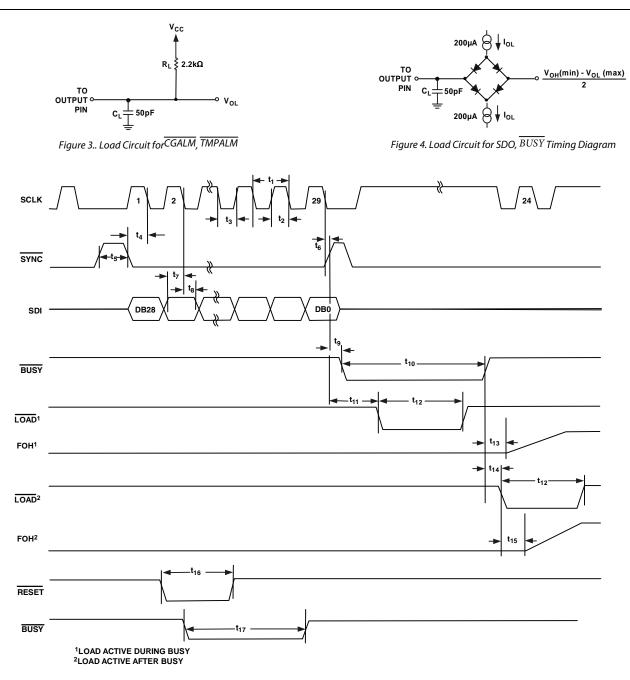
<sup>1</sup> Guaranteed by design and characterization, not production tested.

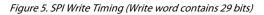
<sup>2</sup> All input signals are specified with  $t_r = t_f = 2$  ns (10% to 90% of V<sub>cc</sub>) and timed from a voltage level of 1.2 V. <sup>3</sup>See Figure 5 and Figure 6

<sup>4</sup>This is measured with load circuit of Figure 4

 ${}^{\rm 5}$ SDO output gets slower with lower DV<sub>CC</sub> supply and may require use of slower SCLK.

# **Preliminary Technical Data**





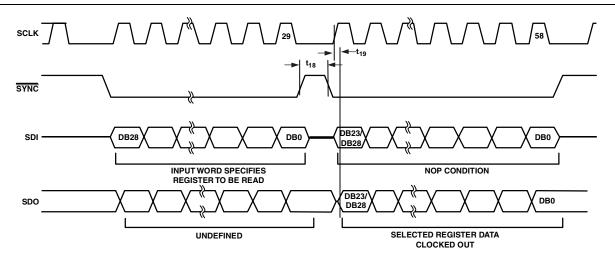


Figure 6. SPI Read Timing (Readback word contains 24 bits and can be clocked out with a minimum of 24 clock edges)

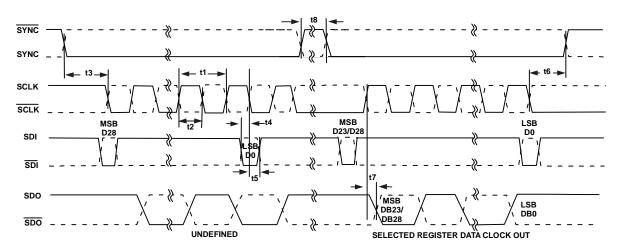


Figure 7. LVDS Read and Write Timing, (Readback word contains 24 bits and can be clocked out with a minimum of 24 clock edges)

### AD5522

# **ABSOLUTE MAXIMUM RATINGS**

Table 3. AD5522 Absolute Maximum Ratings

Parameter	Rating
Supply Voltage AV <sub>DD</sub> to AV <sub>SS</sub>	34V
AV <sub>DD</sub> to AGND	-0.3V to 34V
AV <sub>ss</sub> to AGND	0.3V to -34V
V <sub>REF</sub> to AGND	-0.3 V, +7V
DUTGND to AGND	AV <sub>DD</sub> +0.3V to AV <sub>SS</sub> -0.3V
REFGND to AGND	$AV_{DD}$ +0.3V to $AV_{SS}$ -0.3V
DV <sub>cc</sub> to DGND	- 0.3V to 7V
AGND to DGND	- 0.3V to +0.3V
Digital Inputs to DGND	- 0.3V to DV <sub>cc</sub> +0.3V
Analog Inputs to AGND	$AV_{SS}$ - 0.3V to $AV_{DD}$ +0.3V
Storage Temperature	–65°C to +125°C
Operating Junction Temperature	+25 to +90°C
Reflow Soldering	
Peak Temperature	230°C
Time at Peak Temperature	10s to 40s
Junction Temperature	150°C max

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other condition s above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **THERMAL RESISTANCE<sup>3</sup>**

Thermal resistance values are specified for the worst-case conditions, i.e., specified for device soldered in circuit board for surface mount packages.

### Table 4. Thermal Resistance (JEDEC 4 layer (1S2P) board)

Air Flow (LFPM)		0	200	500	Unit
TQFP Exposed Pad Down	θја	22.3	17.2	15.1	°C/W
	οιθ	4.8			°C/W
TQFP Exposed Pad Up	Αιθ	TBD	TBD	TBD	°C/W
	эιθ	2			°C/W

Table 5. Thermal Resistance (JEDEC 4 layer (1S2P) board with cooling plate<sup>4</sup> at 45°C, natural convection at 55°C ambient)

Package Thermals	θιΑ	οισ	Unit
TQFP Exposed Pad Down	5.4	4.8	°C/W
TQFP Exposed Pad Up	3.0	2	°C/W

<sup>3</sup> Simulated Thermal information.

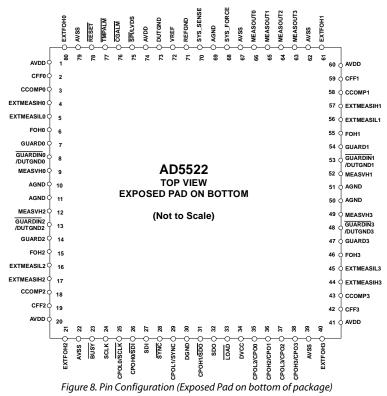
<sup>4</sup> Assumes perfect thermal contact between cooling plate and exposed paddle

### **ESD CAUTION**

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although this product features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



# PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



Pin No.	Pin No.	Mnemonic	Description
Bottom	Тор	Exposed Pad	The exposed pad is electrically connected to AVss.
			TQFP with exposed pad on BOTTOM: For enhanced thermal, electrical and board level performance, the exposed paddle on the bottom of the package should be soldered to a corresponding thermal land paddle on the PCB.
22, 39, 62, 67, 79,	2, 14, 19, 42,59,	AV <sub>SS</sub> (0-4)	Negative analog supply voltage
1, 20, 41, 60, 74	7, 21, 40, 61, 80	AV <sub>DD</sub> (0-4)	Positive analog supply voltage
33	48	LOAD	Active low logic input used for synchronizing updates within one device or across a group of devices. If synchronization is not required, LOAD may be tied low and updates to DAC channels or PMU modes will happen as they are presented to the device. See the BUSY and LOAD FUNCTIONS section for detailed information.
34	47	DVcc	Digital supply voltage
10, 11, 50, 51, 69	12, 30, 31, 70, 71	AGND	Analog ground, reference points for force and measure circuitry
30	51	DGND	Digital ground reference point.
23	58	BUSY	Open Drain active low input/output indicating the status of interface.
24	57	SCLK	Clock input, active falling edge
25	56	CPOL0/ SCLK	Comparator output low in SPI mode and SCLK in LVDS interface mode
26	55	CPOH0/ SDI	Comparator output high in SPI mode and SDI in LVDS interface mode
27	54	SDI	Serial data input
28	53	SYNC	Frame sync, active low
29	52	CPOL1/ SYNC	Comparator output low in SPI mode and SYNC in LVDS interface mode
31	50	CPOH1/SDO	Comparator output high in SPI mode and SDO in LVDS interface mode

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32	49	SDO	Serial data out, for readback and diagnostic purposes
35	46	CPOL2/CPO0	Comparator output Low, comparator window in LVDS interface mode
36	45	CPOH2/CPO1	Comparator output Low, comparator window in LVDS interface mode
37	44	CPOL3/CPO2	Comparator output Low, comparator window in LVDS interface mode
38	43	CPOH3/CPO3	Comparator output Low, comparator window in LVDS interface mode
66, 65, 64,	15, 16, 17,	MEASOUT(0-3)	Multiplexed DUT voltage/Current sense output/temperature sensor voltage per channel,
63	18		referenced to AGND.
68	13	SYS_FORCE	External FORCE signal input, enables connection of system PMU.
70	11	SYS_SENSE	External SENSE signal output, enables connection of system PMU.
71	10	REFGND	Accurate analog reference input ground.
72	9	VREF	Reference Input for DAC channels, 5V for specified performance.
75	6	SPI/LVDS	Interface select pin. Logic low selects SPI interface compatible mode, logic high selects LVDS interface mode. In LVDS mode the CPOH(0-3) pins default to differential interface pins.
76	5	CGALM	GALM is an open drain pin providing shared Alarm information for Guard amplifier and Clamp circuitry.By default, this output pin is disabled. The System Control Register allows user to enable this function and to set the open drain output as a latched output, or to configure either the Guard or Clamp function or both flagging the alarm pin.When this pin flags an alarm, the origins of the alarm may be determined by reading back the Alarm Status Register. Two flags per channel in this word (one latched, one unlatched) indicate which function caused the alarm and if the alarm is still present.
77	4	TMPALM	The function of this pin is to flag a Temperature Alarm. It is a latched active low open drain output indicating the junction temperature has exceeded either the programmed or default (130degC) temperature setting.
			Two flags in the Alarm Status Register (one latched, one unlatched) indicate if the temperature has dropped below 130degC or still above. User action is required to clear this latched alarm flag, by writing to the "CLEAR" bit in any of the PMU registers.
78	3	RESET	Active low, level sensitive input used to reset all internal nodes on the device to their power-on reset value.
3, 18, 43, 58	78, 63, 38, 23	С <sub>СОМР</sub> (0-3)	Compensation capacitor Input per channel. See section on compensation capacitors
2, 19, 42, 59	79, 62, 39, 22	C <sub>FF</sub> (0-3)	External capacitor optimizing the stability performance of the force amplifier (per channel) See section on Compensation Capacitors
80, 21, 40, 61	1, 60, 41, 20	EXTFOH(0-3)	Per channel, Force output for high current range. Use external resistor here for current range up to 64mA.
6, 15, 46, 55	75, 66, 35, 26	FOH(0-3)	Per channel force output for all other ranges.
4, 17, 44, 57	77, 64, 37, 24	EXTMEASIH(0-3)	Per channel sense input (high sense) for high current range.
5, 16, 45, 56	76, 65, 36, 25	EXTMEASIL(0-3)	Per channel sense input (Low sense) for high current range.
9, 12, 49, 52	72, 69, 32, 29	MEASVH(0-3)	Per channel DUT voltage sense input (high sense)
73	8	DUTGND	DUT voltage sense input (low sense). By default, DUTGND is shared between all four PMU channels. If user requires a DUTGND input per channel, the GUARDIN (0-3)/DUTGND(0-3) pin may be configured to be a DUTGND input per each PMU channel.
7, 14 , 47, 54	74, 67, 34, 27	GUARD (0-3)	Guard output drive.
8, 13, 48, 53	73, 68, 33, 28	GUARDIN(0-3) /DUTGND(0-3)	This pin has dual functionality; it may be either a Guard input per channel or DUTGND per channel. Its function is determined via the serial interface. The power on default is GUARDIN, where it functions as the input to the Guard Amplifier. Alternatively, it may be configured to be used as a DUTGND input per channel. In this case, the input to the Guard amplifier is internally connected to MEASVH and the GUARDIN/DUTGND pin is used as a DUTGND input per channel. See section on Guard Amplifier

# **Preliminary Technical Data**

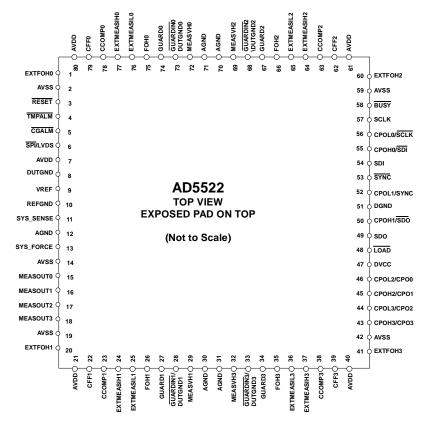


Figure 9. Pin Configuration (Exposed Pad on Top of package)

### TERMINOLOGY

### **Offset Error**

Offset error is a measure of the difference between actual and ideal voltage expressed in mV.

Gain Error Gain error is the difference between full-scale error and zero-scale error. It is expressed in %.

*Gain Error = Full-Scale Error – Zero-Scale Error* **Linearity Error** 

Relative accuracy, or endpoint linearity, is a measure of the maximum deviation from a straight line passing through the endpoints of the full-scale range. It is measured after adjusting for offset error and gain error and is expressed in % FSR.

### **CM Error**

Common Mode Error is the error at the output of the amplifier due to the common mode input voltage. It is expressed in % of FSR/V.

### **Clamp Accuracy**

Clamp accuracy is a measure of where the clamps begin to function fully and limit the clamped voltage or current.

### Leakage Current

Current measured at an output pin, when that function is off or high impedance.

### **Pin Capacitance**

Capacitance measured at a pin when that function is off or high impedance.

### Slew Rate

The rate of change of output voltage, expressed in V/µs.

### DAC SPECIFIC TERMS

### **Differential Nonlinearity**

Differential nonlinearity is the difference between the measured change and the ideal 1 LSB change between any two adjacent codes. A specified differential nonlinearity of ±1LSB maximum ensures monotonicity.

### **Output Voltage Settling Time**

The amount of time it takes for the output of a DAC to settle to a specified level for a full-scale input change.

### Digital-to-Analog Glitch Energy

The amount of energy injected into the analog output at the major code transition. The area of the glitch in is specified in nV-s. It is measured by toggling the DAC register data between 0x1FFF and 0x2000.

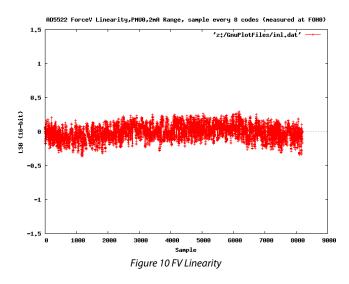
### **Digital Crosstalk**

The glitch impulse transferred to the output of one converter due to a change in the DAC register code of another converter is defined as the digital crosstalk and is specified in nV-s.

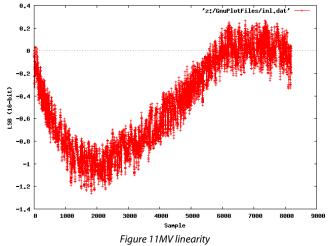
### **Digital Feedthrough**

When the device is not selected, high frequency logic activity on the device's digital inputs can be capacitively coupled both across and through the device to show up as noise on the VOUT pins. It can also be coupled along the supply and ground lines. This noise is digital feedthrough.

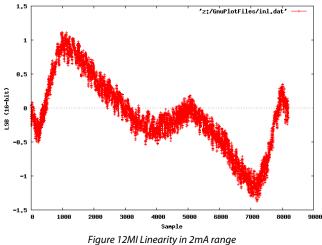
# **TYPICAL PERFORMANCE CHARACTERISTICS**



AD5522 FVMV Linearity,PMU0,2mA Range, sample every 8 codes (measured at MEASOUT0)



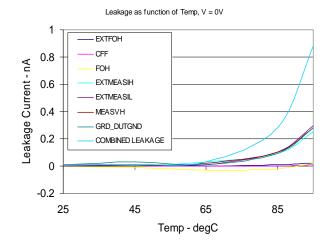
AD5522 MeasI Linearity,PMU0,2mA Range, sample every 8 codes (measured at MEASOUT0)

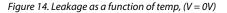


Leakage as function of Temp, V = 12V 2 EXTFOR CFF 1.5 FOH Leakage Current - nA EXTMEA SIH EXTMEASIL 1 MEASVH GRD\_DUTGND 0.5 COMBINED LEAKAGE 0 -0.5 45 75 95 25 35 55 65 85

Figure 13Leakage as a function of Temperature (V = 12V).

Temp - degC





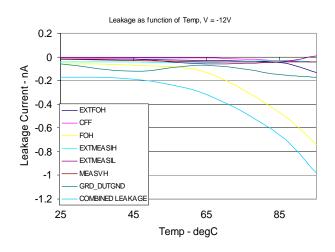


Figure 15. Leakage as a function of temp, (V = -12V)

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# **Preliminary Technical Data**

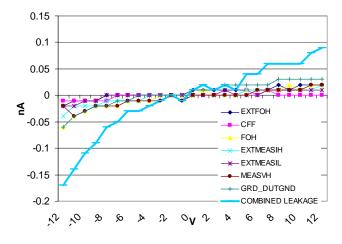


Figure 16. Leakage as a function of voltage (25degC).

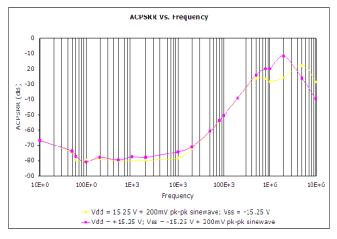
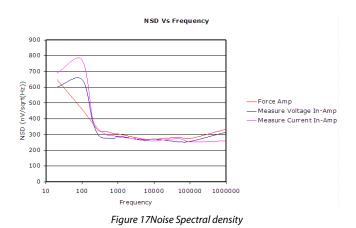


Figure 18. ACPSRR versus Frequency



# **FUNCTIONAL DESCRIPTION**

The AD5522 is a highly integrated quad per pin parametric measurement unit (PPMU) for use in semiconductor automatic test equipment. It contains programmable modes to force a pin voltage and measure the corresponding current (FVMI), force current measure voltage (FIMV), force current measure current (FIMI), force voltage measure voltage (FVMV) and force nothing measure voltage (FNMV) or measure current (FNMI). The PPMU can force or measure a voltage range of 22.5 V. It can force or measure currents ranging up to 64mA per channel using the internal amplifier, while the addition of an external amplifier enables higher current ranges. On Chip are all the DAC levels required for each PMU channel.

### FORCE AMPLIFIER

The force amplifier drives the analog output FOH, which drives a programmed current or voltage to the DUT (device under test). Headroom and footroom requirements for this amplifier is 3V on either end. An additional  $\pm 1$ V is dropped across the sense resistor when maximum current is flowing through it.

This amplifier is designed to drive DUT capacitances up to 10nF, with a compensation value of 100pF. Larger DUT capacitive load will require larger compensation capacitances.

Local feedback ensures the amplifiers are stable when disabled. A disabled channel reduces power consumption by 2.5mA/channel.

### COMPARATORS

Per channel, the DUT measured value is monitored by two comparators configured as window comparators. Internal DAC levels set the CPL and CPH (low and high) threshold values. There are no restrictions on the voltage settings of the comparator high and lows. CPL going higher than CPH is not a useful operation; however, it will not cause any problems to the device. CPOL and CPOH are continuous time comparator outputs.

Table 7. Comparator Output Function

TEST CONDITION	CPOL	СРОН
V <sub>DUT</sub> or I <sub>DUT</sub> > CPH		0
V <sub>DUT</sub> or I <sub>DUT</sub> < CPH		1
V <sub>DUT</sub> or I <sub>DUT</sub> > CPL	1	
V <sub>DUT</sub> or I <sub>DUT</sub> < CPL	0	
CPH > V <sub>DUT</sub> or I <sub>DUT</sub> > CPL	1	1

When using SPI interface, full comparator functionality is available. When using the LVDS interface, the comparator function is limited to one output per comparator, due to the large pin count requirement of the LVDS interface. In this case, comparator output available CPO (0-3) provides information on whether the measured voltage or current is inside or outside the set CPH and CPL window. Information of whether the measurement was high or low is available via the serial interfaces (Comparator Status Register).

Table 8. Comparator Output Function using LVDS interface

TEST CONDITION	CPO Output
$CPL < V_{DUT} And I_{DUT} < CPH$	1
$CPL > V_{DUT}$ or $I_{DUT} > CPH$	0

### CLAMPS

Current and voltage clamps are included on chip per PMU channel. They protect the DUT in the event of an open or a short. Internal DAC levels set the CLL and CLH (low and high) levels and the clamps work to limit the force amplifier in the event of a voltage or current at the DUT exceeding the set levels. The clamps also function to protect the DUT when a transient voltage or current spike occurs when changing to a different operating mode or when programming the device to a different current range.

The voltage clamps are active while forcing current and the current clamps are active while forcing voltage. By default, the current clamps are off. Simply set them up via the status register through the serial interface. The voltage clamps are always active in FI mode.

If a clamp level has been hit, this will be flagged via the  $\overline{CGALM}$  open drain output and the resulting alarm information may be read back via the SPI or LVDS interface. CLL should never be greater than CLH.

### **CURRENT RANGE SELECTION**

Integrated thin film resistors minimize external components and allow easy selection of current ranges from 5  $\mu$ A (200k $\Omega$ ), 20 $\mu$ A (50k $\Omega$ ), 200 $\mu$ A (5k $\Omega$ ) and 2mA (500 $\Omega$ ). Per channel, one current range up to 64mA may be accommodated by connecting an external sense resistor. For current ranges in excess of 64mA, it is recommended an external amplifier be used.

For the suggested current ranges, the maximum voltage drop across the sense resistors is  $\pm 1$ V, however, to allow for correction of errors, there is some over range available in the current ranges. The full-scale voltage range that can be loaded to the DAC is  $\pm 11.5$ V; the forced current may be calculated as follows:

$$FI = \frac{VFIN}{RSENSE \times Gain}$$

Where:

FI = Forced Current

 $\label{eq:VFIN} \begin{array}{l} \mbox{VFIN} = \mbox{Voltage of the FIN DAC, See } V_{\mbox{OUT}} \mbox{ for DAC levels.} \\ \mbox{RSENSE} = \mbox{Selected Sense Resistor} \end{array}$ 

Gain of Current Measure Instrumentation amplifier, it may be set (via the serial interface) to 5 or 10.

Using the  $5k\Omega$  sense resistor and ISENSE gain of 10, the maximum current range possible is  $\pm 225\mu$ A. Similarly for the other current ranges, there is an over range of 12.5% to allow for correction.

Also, the forced current range will only be the quoted full scale range with an applied reference of 5V or 2.5V (with ISENSE AMP gain = 5). The ISENSE amplifier is biased by the Offset DAC output voltage, in such as way as to center the Measure current output irrespective of the voltage span used.

When using the EXTFOHx outputs for current ranges up to 64mA, there is no switch in series with the EXTFOHx line, ensuring minimum capacitance presented at the output of the force amplifier. This is also an important feature if using a Pin electronics driver to provide high current ranges.

### **HIGH CURRENT RANGES**

With the use of an external high current amplifier, one high current range in excess of 64mA is possible. The high current amplifier simply buffers the force output and provides the drive for the required current.

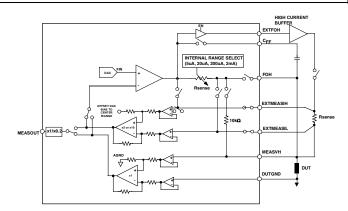


Figure 19. Addition of high current amplifier for wider current range(>64mA)

### **DEVICE UNDER TEST GROUND (DUTGND)**

By default, there is one DUTGND input available for all four PMU channels. In some applications of a PMU, it is necessary that each channel operate from its own DUTGND level. Therefore the shared pin GUARDIN(0-3)/DUTGND(0-3) may be configured as either the input to the GUARD amplifier (GUARDIN), or as a DUTGND per channel function.

This may be configured through the serial interface on power on as per required operation. The default connection is SW13b (GUARDIN) and SW14b (DUTGND PER DEVICE).

When configured as DUTGND per channel, this multifunction pin is no longer connected to the input of the guard amplifier, instead it is connected to the low end of the instrumentation amplifier (SW14a), and the input of the Guard amplifier is now connected internally to MEASVH (SW13a).

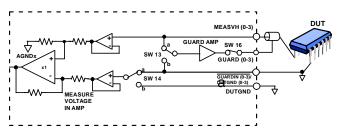


Figure 20. Using the DUTGND per channel Feature

### **GUARD AMPLIFER**

A Guard amplifier allows the user to bootstrap the shield of the cable to the voltage applied to the DUT, ensuring minimal drops across the cable. This is particularly important for measurements requiring a high degree of accuracy and in leakage current testing.

If not required, all four Guard Amplifiers may be disabled via the serial interface (through the System Control Register), this decreases the power consumption by 400uA per channel.

As described in the DUTGND section, the GUARDIN(0-3) /DUTGND(0-3) is a shared pin. It can function either as a guard amplifier input per channel or as a DUTGND input per channel as required by the end application. Refer to Figure 20.

A Guard alarm event occurs when the guard output moves more than 100mV away from the Guard input voltage for more than 200 $\mu$ s. In the event this happens, this will be flagged via the CGALM open drain output. As the guard and clamp alarm functions share the same alarm outputCGALM, the alarm information (alarm trigger and alarm channel) is available via the serial interface (ALARM STATUS REGISTER).

Alternatively, the serial interfaces allow the user to setup the  $\overline{CGALM}$  output to flag either the clamp status or the guard status. By default, this open drain alarm pin is an unlatched output, but may be set to a latched output via the serial interface, System Control Register.

### **COMPENSATION CAPACITORS**

Each channel requires an external compensation capacitor  $(C_{COMP})$  to ensure stability into the maximum load capacitance while ensuring settling time is optimized. In addition, one  $C_{FF}$  pin is provided to further optimize stability and settling time performance when in Force voltage mode. When changing from Force current to force voltage mode, the switch connecting  $C_{FF}$  capacitor is automatically closed. While the force amplifier is designed to drive load capacitances up to 10nF (with Ccomp = 100pF), using larger compensation capacitor values, it is possible to drive larger load at the expense of an increase in settling time. If a wide range of load capacitance must be driven, then an external multiplexer connected to the  $C_{COMP}$  pin will allow optimization of settling time versus stability. The series resistance of a switch placed on  $C_{COMP}$ , should typically be <50 $\Omega$ .

Similarly, connecting the  $C_{FF}$  node to a multiplexer externally, would cater for a wide range of CDUT in Force Voltage mode. The series resistance of the multiplexer used should be such that:



**Table 9. Suggested Compensation Capacitor Selection** 

CLOAD	C <sub>COMP</sub>	C <sub>FF</sub>
≤lnF	100pF	220pF
≤10nF	100pF	lnF
≤100nF	CLOAD/100	CLOAD/10

### SYSTEM FORCE SENSE SWITCHES

Each channel has switches to allow connection of the force (FOHx) and sense (MEASVHx) lines to a central PMU for calibration purposes. There is one set of SYS\_FORCE and SYS\_SENSE pins per device. For calibration purposes, it is recommended the SYS\_FORCE path be connected individually to each PMU channel, FOH path.

### **TEMPERATURE SENSOR**

An on board temperature sensor monitors temperatures and in the event of the temperature exceeding a factory defined value,  $(130^{\circ}C)$  or a user programmable value, the device will protect itself by shutting down all channels and will flag an alarm through the latched open drain TMPALM pin. Alarm status may be readback from the Alarm Status Register or the PMU registers where latched and unlatched bits tell if an alarm has occurred and whether the temperature has dropped below the set alarm temperature.

### **MEASURE OUTPUT (MEASOUT)**

The measured DUT voltage or current (voltage representation of DUT current) is available on MEASOUT (0-3) with respect to AGND. The default MEASOUT range is the forced voltage range for voltage measure and current measure (nominally  $\pm$ 11.25V, depends on reference voltage and offset DAC) and includes some over range to allow for offset correction. The serial interface allows the user to select another MEASOUT range of V<sub>REF</sub> to AGND, allowing for a smaller input range ADC to be used. Each PMU channel MEASOUT line may be made high impedance via the serial interface.

When using low supply voltages, ensure that there is sufficient headroom and footroom for the required force voltage range.

The Offset DAC also directly offsets the MEASURE output voltage level, but only when GAIN1 = 0.

MEA	SOUT Function	l	$GAIN1 = "0"V_{REF} = 5V$	GAIN1 = "1"			
			MEASOUT Gain = 1	MEASOUT Gain = 1/5			
MV			±VDUT (up to 11.25V)	$0 \text{ to} \frac{4.5 \text{VREF}}{5}$			
МІ	GAIN0 = "0"	CURRENT MEAS GAIN = 10	$\pm V_{RSENSE} X 10 = up to \pm 11.25V$	0 to 4.5V			
	GAIN0 = "1"	CURRENT MEAS GAIN = 5	$\pm$ V <sub>RSENSE</sub> X 5 = up to $\pm$ 5.625	0 to 2.25V			

### Table 10. MEASOUT Output Ranges

## DAC LEVELS

Each channel contains five dedicated DAC levels : one for the force amplifier, one each for the clamp high and low levels and one each for the comparator high and low levels.

The architecture of a single DAC channel consists of a 16-bit resistor-string DAC followed by an output buffer amplifier. This resistor-string architecture guarantees DAC monotonicity. The 16-bit binary digital code loaded to the DAC register determines at what node on the string the voltage is tapped off before being fed to the output amplifier.

The transfer function for DAC outputs is:

$$V_{OUT} = 4.5 V_{REF} \left( \frac{DACCODE}{2^{16}} \right) - 3.5 V_{REF} \left( \frac{OFFSETDAC \cdot CODE}{2^{16}} \right) + DUTGND$$

Where the voltage range must be take into account the +/-4V headroom and footroom requirements for the amplifier and sense resistor and must be within the range -16.25V to 22.5V (22V range + 500mV overrange to allow for correction).

### **OFFSET DAC**

The device is capable of forcing a 22.5V ( $4.5 \times V_{REF}$ ) voltage range. Included on chip is one 16 Bit offset DAC (one for all four channels) which allows for adjustment of the voltage range.

The useable range is -16.25V to 22.5V. Zero scale gives a fullscale range of 0V to +22.5V, mid scale gives  $\pm$ 11.25V, while the most negative useful range is in a range of -16.25V to 6.25V. Full scale loaded to the Offset DAC does not give a useful output voltage range as the output amplifiers are limited by available footroom. The following table shows the effect of the Offset DAC on the other DACs in the device.

# Table 11. OFFSET DAC Relationship with other DACs with $$V_{\mbox{\scriptsize REF}}$=5V$$

Offset DAC	DAC Code	DAC Output Voltage Range
Code		
0	0	0.00 V
0	32768	11.25 V
0	65535	22.50 V
32768	0	-8.75 V
32768	32768	2.50 V
32768	65535	13.75 V
42130	0	-11.25 V
42130	32768	0.00 V
42130	65535	11.25 V
60855	0	-16.25
60855	32768	-5.00
60855	65535	6.25
65535	-	Footroom Limitations

Therefore, depending on headroom available, the input to the Force Amplifier may be unipolar positive, or bipolar, either symmetrical or asymmetrical about DUTGND but always within a voltage span of 22.5V.

The offset DAC offsets all DAC functions. It also centers the current range, such that zero current always flows at midscale code irrespective of offset DAC setting.

Rearranging the transfer function for the DAC output gives the following equation to determine what Offset DAC code is required for a given reference and output voltage range.

$$OFFSETDACCODE = \left(\frac{2^{16}(V_{OUT} - DUTGND)}{3.5V_{REF}}\right) - \left(\frac{4.5 \times DACCODE}{3.5}\right)$$

### **OFFSET AND GAIN REGISTERS**

Each DAC level contains independent offset and gain control registers that allow the user to digitally trim offset and gain. These registers give the user the ability to calibrate out errors in the complete signal chain, including the DAC, using the internal m and c registers, which hold the correction factors. All registers in the AD5522 are volatile, so need to be loaded on power on during a calibration cycle.

The digital input transfer function for each DAC can be represented as

$$x2 = [(m+1)/2^n \times x1] + (c - 2^{n-1})$$

where:

 $x^2$  = the data-word loaded to the resistor string DAC. xI = the 16-bit data-word written to the DAC input register. m = code in gain register (default code = 2<sup>16</sup> – 1.) c = code in offset register (default code = 2<sup>15</sup>) n = DAC resolution (n = 16). The calibration engine is only engaged when data is written to

the x1 register. This has the advantage of minimizing the setup time of the device.

### **CACHED X2 REGISTERS**

Each DAC has a number of cached x2 values. These registers store the result of an offset and gain calibration in advance of a mode change. This enables the user to preload registers; allow the calibration engine to calculate the appropriate x2 value and store until ready to change modes. As the data is ready and held in the appropriate register, this enables mode changing be as time efficient as possible. If an update occurs to a DAC register set that is currently part of the operating PMU mode, the DAC output will update immediately (depending on LOAD condition).

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### Offset and Gain registers for the FIN DAC

The FIN (force amplifier input) DAC level contains independent offset and gain control registers that allow the user to digitally trim offset and gain. There are six sets of x1, m and c registers, one set (x1, m and c) for the force voltage range, and one set for each of the force current ranges (4 internal current ranges and 1 external current range). Six x2 registers store calculated DAC values ready to load to the DAC register on a mode change.

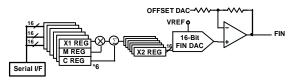


Figure 21. FIN DAC Registers

### Offset and Gain registers for the COMPARATOR DACs

The Comparator DAC levels contain independent offset and gain control registers that allow the user to digitally trim offset and gain. There are six sets of (x1, m and c) registers, one set for the voltage mode, and one set for each of the four internal current ranges and one set for the external current range. In this way, x1 may also be preprogrammed, so switching different modes, allows for efficient switching into the required compare mode. Six x2 registers store cached calculated DAC values ready to load to the DAC register on a mode change.

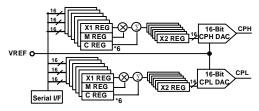


Figure 22. Comparator Registers

### Offset and Gain registers for the Clamp DACs

The clamp DAC levels contain independent offset and gain control registers that allow the user to digitally trim offset and gain. There are just two sets of registers, one for the voltage mode and another register set (x1, m and c) for all five current ranges. Two x2 registers store cached calculated DAC values ready to load to the DAC register on a PMU mode change.

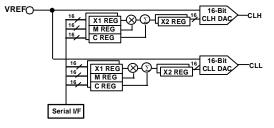


Figure 23. Clamp Registers

### $V_{REF}$

One buffered analog input supplies all 20 DACs with the necessary reference voltage to generate the required DC levels.

### **REFERENCE SELECTION**

The voltage applied to the  $V_{REF}$  pin determines the output voltage range and span applied to the force amplifier, clamp and comparator inputs. This device can be used with a reference input ranging from 2V to 5V, however, for most applications, a reference input of 5V or 2.5V will be sufficient to meet all voltage range requirements. The DAC amplifier gain is 4.5, which gives a DAC output span of 22.5V. The DACs have offset and gain registers which can be used to calibrate out system errors.

In addition, the gain register can be used to reduce the DAC output range to the desired force voltage range. The Force DAC will retain 16 bit resolution even with a gain register setting of quarter scale (0x4000). Therefore, from a single 5V reference, it is possible to get a voltage span as high as 22.5V or as low as 5.625V all from one 5V reference.

When using the offset and gain registers, the chosen output range should take into account the system offset and gain errors that need to be trimmed out. Therefore, the chosen output range should be larger than the actual, required range.

When using low supply voltages, ensure that there is sufficient headroom and footroom for the required force voltage range. Also, note that with a supply differential of less than 18V and a full scale current range requirement, it is necessary to reduce the current measure in amp gain to 5 so the feedback path can swing through the full range.

Also, the forced current range will only be the quoted full scale range with an applied reference of 5V or 2.5V (with ISENSE AMP gain = 5).

For other voltage/current ranges, the required reference level can be calculated as follows:

- 1. Identify the nominal range required
- 2. Identify the maximum offset span and the maximum gain required on the full output signal range.
- 3. Calculate the new maximum output range including the expected maximum offset and gain errors.
- Choose the new required VOUT<sub>max</sub> and VOUT<sub>min</sub>, keeping the VOUT limits centered on the nominal values. Note that AV<sub>DD</sub> and AV<sub>SS</sub> must provide sufficient headroom.
- 5. Calculate the value of  $V_{\text{REF}}$  as follows:  $V_{\text{REF}} = (VOUT_{MAX} - VOUT_{MIN})/4.5$

### **Reference Selection Example**

Nominal Output Range = 10V (-2V to +8V)Offset Error =  $\pm 100mV$ Gain Error =  $\pm 0.5\%$ REFGND = AGND = 0V

- Gain Error = ±0.5%
   => Maximum Positive Gain Error = +0.5%
   => Output Range incl. Gain Error
   = 10 + 0.005(10)=10.05V
- 2) Offset Error = ±100mV
   => Maximum Offset Error Span = 2(100mV)=0.2V
   => Output Range including Gain Error and Offset Error = 10.05V + 0.2V = 10.25V
- 3)  $V_{REF}$  Calculation Actual Output Range = 10.25V, that is -2.125V to +8.125V (centered);  $V_{REF} = (8.125V + 2.125V)/4.5 = 2.28V$

If the solution yields an inconvenient reference level, the user can adopt one of the following approaches:

- 1. Use a resistor divider to divide down a convenient, higher reference level to the required level.
- 2. Select a convenient reference level above  $V_{REF}$  and modify the Gain and Offset registers to digitally downsize the reference. In this way the user can use almost any convenient reference level.
- 3. Use a combination of these two approaches

In this case, the optimum reference to choose is a 2.5V reference, then use the m and c registers and the OFFSET DAC to achieve the required -2V to +8V range. The ISENSE amplifier gain should be changed to a gain of 5. This ensures a full scale current range of the specified values and also allows optimization of power supplies and minimizes power consumption within the device.

### CALIBRATION

The user can perform a system calibration by overwriting the default values in the m and c registers for any individual DAC channels as follows:

Calculate the nominal offset and gain coefficients for the new output range (see previous example)

Calculate the new m and c values for each channel based on the specified offset and gain errors

### **Calibration Example**

Nominal Offset Coefficient = 32768 Nominal Gain Coefficient = 10/10.25x 65535 = 63937

### 12/12.26× 65535 = 64145

### Example 1: Gain Error = +0.5%, Offset Error = +100mV

1) Gain Error (0.5%) Calibration: 63937 × 0.995 = 63617 => Load Code "0b1111 1000 1000 0001" to m register

### 2) Offset Error (100mV) Calibration:

 $LSB \ Size = 10.25/65535 = 156 \ \mu V; \\ Offset \ Coefficient \ for \ 100mV \ Offset = 100/0.156 = 641 \ LSBs \\ => \ Load \ Code \ "0b0111 \ 1101 \ 0111 \ 1111" \ to \ c \ register$ 

### SYSTEM LEVEL CALIBRATION

There are many ways to calibrate the device on power on. The following gives an example of how to calibrate the FIN DAC of the device without a DUT or DUT board connected. Calibration Procedure for Force and Measure circuitry:

- Calibrate Force Voltage (2 point) Write zero scale to the Force DAC (FIN), connect SYS\_FORCE to FOHx and SYS\_SENSE to MEASVHx, close the internal Force/Sense Switch (SW 7). Using the System PMU, measure the error between voltage at FOHx, MEASVHx and desired value. Similarly, load Full scale to the Force DAC, and measure the error between FOHx , MEASVH and the desired value. Work out m and c values. Load these values to appropriate m and c registers for Force DAC.
- 2) Calibrate Measure Voltage (2 point) Connect SYS\_FORCE to FOH, SYS\_SENSE to MEASVHx Close Internal Force/Sense switch (SW 7). Force voltage on FOH via SYS\_FORCE and measure voltage at MEASOUT. The difference is the error between the actual forced voltage and the voltage at MEASOUT.
- Calibrate Force current (2 point) In Force current mode, write zero and fullscale to the Force DAC. Connect SYS\_FORCE to external ammeter and to FOH pin. Measure error on zero and fullscale current and calculate m and c values.
- 4) Calibrate Measure Current (2 Point) Write zero scale to the Force DAC in Force Current mode. Connect SYS\_FORCE to an external ammeter and to the FOH pin. Measure the error between ammeter reading and MEASOUT reading. Repeat with Full scale loaded to the Force DAC.
- 5) Repeat for all four channels.

Similarly, calibrate the comparators and clamp DACs and load the appropriate gain and offset registers. Calibrating these DACs will require some successive approximation to find where the comparator trips or the clamps engage.

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# **CIRCUIT OPERATION**

### FORCE VOLTAGE, FV

Most PMU measurements are performed while in force voltage and measure current mode, for example, when the device is used as a device power supply, or in continuity or leakage testing. In the force voltage mode, the voltage forced is mapped directly to the DUT. The voltage measure amplifier completes the loop giving negative feedback to the forcing amplifier. See Figure 24.

Forced Voltage at DUT = VFIN

### Where:

VFIN = Voltage of the FIN DAC, See  $V_{OUT}$  for DAC levels.

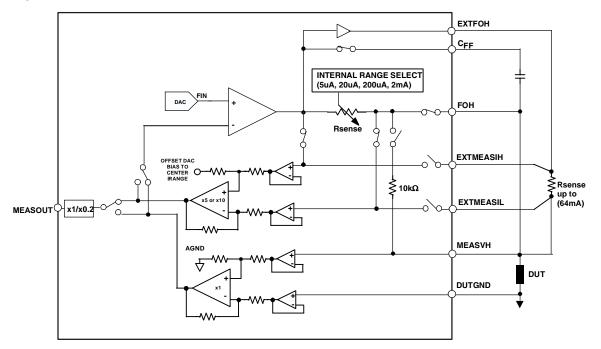


Figure 24. Forcing voltage, measuring current

### FORCE CURRENT, FI

In the force current mode, the voltage at FIN is now converted to a current and applied to the DUT. The feedback path is now the current measure amplifier, feeding back the voltage measured across the sense resistor and MEASOUT reflects the voltage measured across the DUT. See Figure 25.

For the suggested current ranges, the maximum voltage drop across the sense resistors is  $\pm 1$ V, however, to allow for correction of errors, there is some over range available in the current ranges. The maximum full-scale voltage range that can be loaded to the FIN DAC is  $\pm 11.5$ V; the forced current may be calculated as follows:

$$FI = \frac{VFIN}{RSENSE \times Gain}$$

Where:

 $\label{eq:FI} FI = Forced Current \\ VFIN = Voltage of the FIN DAC, See V_{OUT} for DAC levels. \\ RSENSE = Selected Sense Resistor \\ Gain of Current Measure Instrumentation amplifier, it may be set (via the serial interface) to 5 or 10. \\ \end{array}$ 

The ISENSE amplifier is biased by the Offset DAC output voltage, in such as way as to center the Measure current output irrespective of the voltage span used.

Using the  $5k\Omega$  sense resistor and ISENSE gain of 10, the maximum current range possible is  $\pm 225\mu$ A. Similarly for the other current ranges, there is an over range of 12.5% to allow for correction.

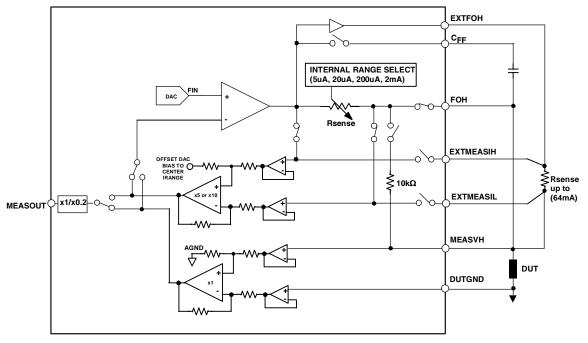


Figure 25. .Forcing current, measuring voltage Rev. PrM | Page 27 of 48

# **SERIAL INTERFACE**

The AD5522 contains two high-speed serial interfaces, an SPI compatible, interface operating at clock frequencies up to 50MHz, and an EIA-644-compliant, LVDS interface. To minimize both the power consumption of the device and on-chip digital noise, the interface powers up fully only when the device is being written to, that is, on the falling edge of SYNC.

### **SPI INTERFACE**

The serial interface operates over a 2.3V to 5.25V  $DV_{CC}$  supply range. The serial interface is controlled by four pin, as follows:

SYNC Frame synchronization input.

SDI Serial data input pin.

SCLK Clocks data in and out of the device.

SDO Serial data output pin for data readback purposes.

There is also an  $\overline{\text{SPI}}/\text{LVDS}$  select pin, which must be held low for SPI interface and high for LVDS interface.

### LVDS INTERFACE

The LVDS interface uses the same input pins as the SPI interface with the same designations. In addition, three other pins are provided for the complementary signals needed for differential operation, thus:

SYNC/SYNC Differential frame synchronization signal.

SDI/SDI Differential serial data input.

SCLK/SCLK Differential clock input.

SDO/SDO Serial data output pin for data readback

### SERIAL INTERFACE WRITE MODE

The AD5522 allows writing of data via the serial interface to every register directly accessible to the serial interface, which is all registers except the DAC registers.

The serial word is 29 bits long. The serial interface works with both a continuous and a burst (gated) serial clock. Serial data applied to SDI is clocked into the AD5522 by clock pulses applied to SCLK. The first falling edge of  $\overline{\text{SYNC}}$  starts the write cycle. At least 29 falling clock edges must be applied to SCLK to clock in 29 bits of data, before  $\overline{\text{SYNC}}$  is taken high again.

The input register addressed is updated on the rising edge of  $\overline{\text{SYNC}}$ . In order for another serial transfer to take place,  $\overline{\text{SYNC}}$  must be taken low again.

### **RESET FUNCTION**

Bringing the level sensitive RESET line low resets the contents of all internal registers to their power-on reset state (detailed in

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the section Power On Default). This sequence takes approx  $300\mu$ s. The falling edge of RESET initiates the reset process; BUSY goes low for the duration, returning high when RESET is complete. While BUSY is low, all interfaces are disabled. When BUSY returns high, normal operation resumes and the status of the RESET pin is ignored until it goes low again. The SDO output will be high impedance during a power on reset or a RESET.

Power on reset follows the same function as  $\overline{\text{RESET}}$ .

### **BUSY AND LOAD FUNCTION**

BUSY is an open drain output that indicates the status of the AD5522 interface. When writing to any of the registers BUSY goes low and stays low until the command completes.

Writing to a DAC register drives the BUSY signal low for longer than a simple PMU or System Control Register write. For the DACs, the value of the internal cached (x2) data is calculated and stored each time the user writes new data to the corresponding x1 register. During this write and calculation, the BUSY output is driven low. While BUSY is low, the user can continue writing new data to the x1, m, or c registers, but no output updates can take place.

X2 values are stored and held until a PMU word is written that calls the appropriate cached x2 register. Only then does a DAC output update.

The DAC outputs and PMU modes are updated by taking the  $\overline{\text{LOAD}}$  input low. If  $\overline{\text{LOAD}}$  goes low while  $\overline{\text{BUSY}}$  is active, the  $\overline{\text{LOAD}}$  event is stored and the DAC outputs or PMU modes update immediately after  $\overline{\text{BUSY}}$  goes high. A user can also hold the  $\overline{\text{LOAD}}$  input permanently low. In this case, the change in DAC outputs or PMU modes update immediately after  $\overline{\text{BUSY}}$  goes high.

The  $\overline{\text{BUSY}}$  pin is bidirectional and has a 50 k $\Omega$  internal pullup resistor. Where multiple AD5522 devices may be used in one system, the  $\overline{\text{BUSY}}$  pins can be tied together. This is useful where it is required that no DAC or PMU in any device is updated until all others are ready. When each device has finished updating the x2 registers, it will release the  $\overline{\text{BUSY}}$  pin. If another device has not finished updating its x2 registers, it will hold  $\overline{\text{BUSY}}$  low, thus delaying the effect of  $\overline{\text{LOAD}}$  going low. As there is only one multiplier shared between four channels, this task must be done sequentially, so the length of the  $\overline{\text{BUSY}}$ pulse will vary according to the number of channels being updated.

### Table 12. BUSY Pulse Width

Action	BUSY Pulse Width (µs max)
Loading data to PMU, System Control Register or Readback	0.27
Loading x1 to any 1 PMU DAC Channel	1.25
Loading x1 to any 2 PMU DAC Channels	1.75
Loading x1 to any 3 PMU DAC Channels	2.25
Loading x1 to any 4 PMU DAC Channels	2.75

 $\overline{BUSY}$  Pulse Width = ((Number of channels +1) × 500ns) + 250ns

 $\overline{\text{BUSY}}$  also goes low during power-on reset and when a falling edge is detected on the  $\overline{\text{RESET}}$  pin.

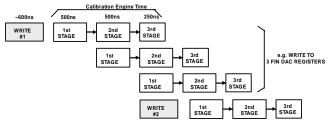


Figure 26. Multiple writes to DAC x1 registers

Writing data to the System control register, PMU control register, m or c registers do not involve the digital calibration engine, thus speeding up configuration of the device on power on.

### **REGISTER UPDATE RATES**

As mentioned previously the value of the X2 register is calculated each time the user writes new data to the corresponding X1 register. The calculation is performed by a three stage process. The first two stages take 500ns each and the third stage takes 250ns. When the writes to one of the X1 registers is complete the calculation process begins. If the write operation involves the update of a single DAC channel the user is free to write to another register provided that the write operation doesn't finish until the first stage calculation is complete, i.e. 500ns after the completion of the first write operation.

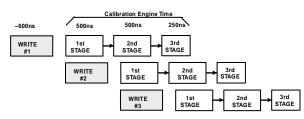


Figure 27. Multiple Single Channel writes engaging calibration engine

### **REGISTER SELECTION**

The serial word assignment consists of 29 bits. Bits 28 through to 22 are common to all registers, whether writing to or reading from the device. PMU3 to PMU0 data bits address each PMU channel (or associated DAC register). When PMU3 to PMU0 are all zeros, the System Control Register is addressed. Mode Bits MODE0 and MODE1 address the different sets of DAC registers and the PMU register.

### Readback Control, RD/WR

The  $R/\overline{W}$  bit set high initiates a readback sequence of PMU, Alarm, Comparator, System Control Register or DAC information as determined by address bits.

### PMU Address Bits, PMU3, PMU2, PMU1, PMU0

Bits PMU3 through PMU0 address each of the PMU channels on chip. This allows individual control of each PMU channel or any manner of combined addressing in addition to multi channel programming. PMU bits also allow access to write registers such as the System Control Register and the many DAC registers, in addition to reading from all the registers.

Table	13.	Mode	Bits
-------	-----	------	------

B23	B22	WRITE FUNCTION								
MODE1	MODE0	Action								
0	0	System Control Register or PMU Register								
0	1	DAC Gain (m) Register								
1	0	DAC Offset (c) Register								
1	1	DAC Input Data Register, (x1)								

B28	B27	B26	B25	B24	B23	B22	B21 to B0	SELECTE	CTED REGISTER				
RD/WR	PMU3	PMU2	PMU1	PMU0	MODE1	MODE0	MODEO DATA BITS CH3 CH2						
WRITE F	UNCTION	IS											
0 0 0 0 0					0	0	DATA BITS	System Con	trol Registe	r (Table 1			
0	0	0	0	0	0	1	DATA BITS	RESERVE	D				
0	0	0	0	0	1	0	DATA BITS	RESERVE	D				
0	0	0	0	0	1	1	11 1111 1111 1111 1111 1111 1111b	NOP (No	Operation)				
0	0	0	0	0	1	1	DATA BITS other than all 1's	RESERVE	D				
WRITE A	DDRESSE	D DAC O	R PMU RE	GISTER									
0	0	0	0	1	Select DAC or F	MU Registers.	DATA BITS	×	×	×	CHO		
0	0	0	1	0	See Table 13			×	×	CH1	×		
0	0	0	1	1				×	×	CH1	CH0		
0	0	1	0	0				×	CH2	×	×		
0	-	-	-	-				-	-	-	-		
0	1	0	0	0				CH3	×	×	×		
0	-	-	-	-				-	-	-	-		
0	1	1	1	0				CH3	CH2	CH1	×		
0	1	1	1	1				CH3	CH2	CH1	CH0		
READ FL	JNCTION	5											
1	0	0	0	0	0	0	All zeros	Read from	m System Co	ontrol Regis	ter		
1	0	0	0	0	0	1	All zeros	Read from	m Compara	tor Status R	egisters		
1	0	0	0	0	1	0	х	Reserved					
1	0	0	0	0	1	1	All zeros	Read from	m Alarm Sta	tus Registe	•		
READ A	DDRESSE	D DAC or	PMU REG	SISTER – C	an only read on	e PMU or DAC re	gister at one time.	-					
1	0	0	0	1	PMU/DAC REG	ISTER ADDRESS	DAC ADDRESS SEE	×	×	×	CH0		
1	0	0	1	0	SEE Table 13		Table 21	×	×	CH1	×		
1	0	1	0	0				×	CH2	×	×		
1	1	0	0	0				CH3	×	×	×		

### NOP (No Operation)

If a NOP (No Operation) command is loaded, no change is made to DAC or PMU registers. This code is useful when performing a read back of a register within the device (via the SDO pin) where a change of DAC code or PMU function may not be required

### **Reserved Commands**

Any bit combination that is not described in the Register address tables for the PMU, DAC and System Control Registers are Reserved commands. These commands are unassigned commands; they are reserved for factory use. To ensure correct operation of the device, do not used reserved commands.

### WRITE SYSTEM CONTROL REGISTER

The System Control Register is accessed when the PMU channel address PMU3-PMU0 and Mode Bits, MODE1 and MODE0 are all zeros. It allows quick setup of different functions within the device. The System Control Register operates on a per device basis.

#### Table 15. System Control Register Bits

B2	8 B2	27 E	B26	B25	B24	B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	B9	B8	<b>B</b> 7	B6	B5	B4	B3	B2	B1/0
RD/WR	PMU3	COWL	PMU2	PMU1	PMU0	MODE1	MODE0	CL3	CL2	CL1	CL0	CPOLH3	CPOLH2	CPOLH1	CPOLH0	CPBIASEN	DUTGND/CH	GUARD ALM	CLAMP ALM	INTIOK	GUARD EN	GAIN1	GAINO	TMP ENABLE	TMP1	TMP0	LATCHED	0

#### Table 16. System Control Register Functions

Bit	Bit name	Descripti	on									
28 (MSB)	RD/WR				•		ted register, while C register as deterr			<b>U</b> .	this initiate	es a readback sequence
27	PMU3	Bits PMU3	8 through	PMU0 a	ddress ea	ch of the PMU	channels in the de	evice. If a	ll four of t	hese bits	are set to a	zero, the System Contro
26	PMU2	Register is			-	-						_
25	PMU1	B27	B26	B25	B24	B23	B22	SELEC	TED REG			
24	PMU0	PMU3	PMU2	PMU1	PMU0	MODE1	MODE0	CH3	CH2	CH1	CH0	
		0	0	0	0	0	0	Write	to Systen	m Control Register		
		0	0	0	1	Select DAC	or PMU Registers.	×	×	×	CHO	
		0	0	1	0	See below		×	×	CH1	×	
		0	0	1	1			×	×	CH1	CH0	
		0	1	0	0			×	CH2	×	×	
		-	-	-	-			-	-	-	-	
		1	0	0	0			CH3	×	×	×	
		-	-	-	-			-	-	-	-	
		1	1	1	0			CH3	CH2	CH1	×	
		1	1	1	1			CH3	CH2	CH1	CH0	
23	MODE1						f the PMU register	or the D	AC gain (n	n), offset (	c ) or input	register (x1). Set to
22	MODE0		-		Control Re	gister.		-				
		MODE1			tion			_				
		0	0			-	or PMU Register	_				
		0	1		AC Gain (m							
		1	0	DA	C Offset (	c) Register						
		1	1	DA	C Input D	ata Register, (	x1)					
SYSTE	M CONTROL REC	GISTER SPE	CIFIC BIT	'S								
21	CL3											0" disables, while a "1"
20	CL2						e in the PMU regist reading back infor					ole function, what was
19	CL1											stem Control Registers.
18	CL0	The Volta	ge clamp	s (Fl mo	de) are alw	ays enabled.						5
17	CPOLH3	Comparat	tor Outpu	ıt Enable	. By defau	It the compar	ator outputs are hi	i-Z on po	wer on. A	"1" in eac	h bit posit	ion enables the
16	CPOLH2											arator functions. The
15	CPOLH1						PMU register on a					lity allows flexible function, what was
14	CPOLH0											m Control Registers.
13	CPBIASEN	Comparat channels,	tor Enable write a "	e. By def 1″ to the	ault the co CPBIASEN	mparators ar bit. A "0" disa	e powered down o	n power tors and	on. To en shuts thei	able the c m down. (	omparato Comparato	r function for all or Output Enables bits
12	DUTGND/CH	DUTGND pin now f	per PMU unctions	channel as a DUT	or GUARD GND pin o	input per PN on a per chanı	1U channel. Setting	g this bit d inputs	to "1" ena are discor	bles DUT( inected fr	GND per ch om this pi	onfigured to enable a nannel. In this mode, th n and instead connecte
11	GUARD ALM	Clamp an	d Guard /	Alarm Fu	nction sha	are one open	drain CGALM alarn	n pin. Bv	default, th	e CGALM	pin is disa	bled. Bits GUARD ALM
10	CLAMP ALM	and CLAN enable eit	1P ALM al	llow the	user to ch	oose if they o	nly wish to have bo	oth or eit	her inforn	nation flag	gged to th	e CGALM pin. Set high
)	INT10K	Internal S		UNIT 4 O								

8	GUARD EN	Guard enable. power (typically				ower on; write a "1" to enable	it. Disabling the guard funct	ion if not in use saves						
7	GAIN1					ults to the voltage force span								
6	GAIN0	$\pm$ 11.25V, which includes some over range to allow for offset correction. The MEASOUT range may be reduced by using the GAIN0 and GAIN1 data bits. This allows for use of asymmetrical supplies and also for use of a smaller input range ADC.												
		MEASOUT Fu	nction			$GAIN1 = "0"V_{REF} = 5V$	GAIN1 = "1"							
						MEASOUT Gain = 1	MEASOUT Gain = 1/5							
		MV				±VDUT (up to 11.25V)	$0 \text{ to } \frac{4.5 \text{VREF}}{5}$							
		MI GAINO:	= "0"	CURRENT M	EAS GAIN = 10	$\pm V_{RSENSE} X 10 = up to \pm 11.25$	V 0 to 4.5V							
		GAIN0	="1"	CURRENT M	EAS GAIN = 5	$\pm$ V <sub>RSENSE</sub> X 5 = up to $\pm$ 5.625	0 to 2.25V							
5	TMP ENABLE	Thermal Shutdown Function, TMP ENABLE, TMP1, TMP0												
4	TMP1	To disable the Thermal Shutdown feature, write a "0" to the TMP ENABLE bit (enabled by default). Bits TMP1 and TMP0 allow the user to program the thermal shutdown temperature of operation.												
3	TMP0	1 3	-		•	e of operation.								
		TMP ENABLE			Action									
		0	Х	Х	Thermal Shute	lown Disabled								
		1	Х	Х	Thermal Shute	lown Enabled								
		1	0	0	Shutdown at J (Power On De	unction Temp of 130°C fault)								
		1	0	1	Shutdown at J	unction Temp of 120°C								
		1	1	0	Shutdown at J	unction Temp of 110°C								
		1	1	1	Shutdown at J	unction Temp of 100°C								
2	LATCHED					ned output pin. When high, th having to poll the line consta								
1	0	Unused bits. Se	t to 0.			· ·	•							
0 (LSB)	0													

### WRITE PMU REGISTER

To address PMU functions, set Mode bits MODE1, MODE0 low, this selects the PMU register as outlined in Table 13 and Table 14. The AD5522 has very flexible addressing, in that it allows writing of data to a single PMU channel, any combination of them or all PMU channels. This enables multi pin broadcasting to similar pins on a DUT. Bits 27 to 24 select which PMU or group of PMUs is addressed.

### Table 17. PMU Register Bits

B28	B27	B26	B25	B24	B23	B22	B21	B20	B19	B18	B17	B16	B15	B14	B13	B12	B11	B10	B9	B8	B7	B6	<b>B5</b> to B0
RD/WR	PMU3	PMU2	PMU1	PMU0	MODE1	MODE0	CH EN	FORCE1	FORCE0	х	C2	C1	C0	MEAS1	MEAS0	FIN	SF0	SF0	CL	CPOLH	Compare V/I	CLEAR	UNUSED DATA BITS

Bit	Bit name	Descri	<u> </u>												
28 (MSB)	RD/WR					•			l register, while if l or DAC register					tes a readback	
27	PMU3	Bits PN	1U3 tł	nrough	٩Μ	J0 address ea	ch of the	PMU ch	annels in the dev	ice. This	allows in	dividual	control o	f each PMU channe	
26	PMU2	or any	manr	ner of c	omb	ined addressi	ng in ado	dition to	multi-channel pr	ogramm	ing.				
25	PMU1	B27	В	326	B2	5 B24	B23		B22	SELE	CTED REC	SISTER			
24	PMU0	PMU	3 P	MU2	PM	U1 PMU0	MODE	1	MODE0	CH3	CH2	CH1	CH0		
		0	0	)	0	0	0		0	Write	to Systen	n Control	Register		
		0	0	)	0	1	Select	DAC or	PMU Registers.	×	×	×	СНО		
		0	0	)	1	0	See be	low	-	×	×	CH1	×		
		0	0	)	1	1				×	×	CH1	CH0		
		0	1		0	0	-			×	CH2	×	×		
			-		-	-	1			-	-	-	-	_	
		1	0		0	0				СНЗ	×	×	×	_	
					-	-	1			-	-	-	-	-	
		1	1		- 1	0	1			- CH3	CH2	- CH1	×	-1	
							1			-	_			_	
22	140051	1     1     1     1     CH3     CH2     CH1     CH0       Mode Bits     MODE0 and MODE1 allow addressing of the PMU register or the DAC gain (m) offset (c) or input													
23	MODE1		Mode Bits, MODE0 and MODE1 allow addressing of the PMU register or the DAC gain (m), offset (c) or input register (x1) to zero to access the PMU Register.												
22	MODE0	MODE1 MODE0 Action													
		0		0			trol Pea	istor or	PMU Register						
		0		1		DAC Gain (m			Fillo Register						
		1		0		DAC Gain (in DAC Offset (									
		1		1			-								
				I		DAC Input D	ata Regis	ster, (x i)							
21	GISTER SPECIFIC CH EN	Chann				h to enable th closed, SW 5		ed chani	nel, similarly, set l	ow to di	sable a se	lected ch	nannel or	group of channels.	
20	FORCE1					-	•	nction fo	or each of the PM	Ilchann	ols (in ass	ociation	with D2_[		
19	FORCEO													rent) modes allows	
19	FORCEU	user to	o optir	mize gl	itch i	response duri	ng mode	change	s. While in these	modes, ۱	vith PMU	Hi-Z, nev	w x1 code	es loaded to the FIN	
		DAC re	egiste	r and t	he Cl	amp DAC reg	ister will	be calib	rated, stored in x	2 registe	r and load	ded direc	tly to the	DAC outputs.	
		FOR	CE1	FOR	CEO	Action									
		0		0		FV & Curren	t Clamp	(if clamp	enabled)						
		0		1		FI & Voltage	e Clamp (	if clamp	enabled)						
		1		0		Hi-Z FOH Vo	oltage (pi	re load F	IN DAC & Clamp	DAC)					
		1		1		Hi-Z FOH Cu	urrent (pi	re load F	IN DAC & Clamp	DAC)					
18	RESERVED	0													
17	C2	Bits C2	throu	ugh C0	add	ress allow sele	ection of	the requ	ired current rang	je.					
16	C1	C2	<b>C</b> 1	<b>C0</b>	Act	ion									
15	C0	0	0	0	±5µ	A current ran	ge								
		0	0	1		)μA current ra									
		0	1	0	±20	) 0µA current r	ange								
		0	1	1		nA current rar	-								
		1	0	0		ternal current									
		1	0	1		erved									
		1	1	0		erved									
				-											
			1 1 1 Reserved												

### Table 18. PMU Register Functions

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14	MEAS1				0 allow selection of the required measure mode nsor or enabled for measurement or current or v		easout line to be disabled, connected
13	MEASO	MEAS		EASO	Action	onage.	
		0	0		MEASOUT connected to I SENSE		
		0	1		MEASOUT connected to V SENSE		
		1	0		MEASOUT connected to Temperature Sensor		
		1	1		MEASOUT Hi-Z (SW 12 Open)		
12	FIN	Bit FIN	= 0 swit	ches th	e input of the force amplifier to GND, while FIN	= 1 connects it to	o FIN DAC output.
11	SFO	Bits SFC	) throug	h SS0 a	address each of the different combinations of sw	itching the syste	em force and sense lines to the force
10	SSO				Selection of which channel the system force and t operation, only one PMU channel should be co		
		SF0	SS0	Actio	n		
		0	0	SYS_F	ORCE and SYS_SENSE Hi-Z		
		0	1	SYS_F	ORCE Hi-Z, SYS_SENSE connected to MEASVHx		
		1	0	SYS_F	ORCE connected to FOHx, SYS_SENSE Hi-Z		
		1	1	SYS_F	ORCE connected to FOHx, SYS_SENSE connecte	d to MEASVHx	
9	CL	functio functio recentl	n is also n. Wher y writte	availal readir n to the	p enable bit. A logic high enables the clamp fun- ble in the System control register. This dual func- ng back information on the status of the clamp e e current clamp register is available in the readba I mode) are always enabled.	tionality allows f nable function c	lexible enable or disabling of this on a per channel basis, what was most
8	CPOLH	CPBIAS	EN mus	t be en	nable bit. A logic high enables the comparator o abled in the SYSTEM CONTROL REGISTER. The cc gister. This dual functionality allows flexible enal	mparator outpu	ut enable function is also available in
7	COMPARE V/I	A logic	high se	ects co	ompare voltage function, while logic low, current	function.	
6	CLEAR				hed alarm bit and pin (temperature, guard or cla np and guard) conditions on all four PMU channe		to the Clear bit position. This bit applies
5	0	Unused	l bits. Se	t to 0.			
4							
3							
2							
1							
0 (LSB)	7						

### WRITE DAC REGISTER

The DAC input, gain and offset registers are addressed through a combination of PMU bits (Bits 27 through 24) and MODE bits (Bits 23 and 22). Bits A5 through A0 address each of the DAC levels on chip. D15 through D0 are the DAC data Bits when writing to these registers. PMU address bits allow addressing to DAC across any combination of PMU channels.

### Table 19. DAC Register Bits

B28	B27	B26	B25	B24	B23	B22	B21	B20	B19	B18	B17	B16	B15 to B0
RD/WR	PMU3	PMU2	PMU1	PMU0	MODE1	MODE0	A5	A4	A3	A2	A1	A0	DATA BITS D15 (MSB to D0 (LSB)

Bit	Bit name	Description											
28 (MSB)	RD/WR						ted register, while if vstem Control or DAC			5,			
27	PMU3						and DAC channels i						
26	PMU2	control o	of each DA	C cha	annel or any r	nanner of com	nbined addressing in	additior	n to multi	-channel	programmii		
25	PMU1	B27	B26	B2	5 B24	B23	B22	SELEC	SELECTED REGISTER				
24	PMU0	PMU3	PMU2	PM	U1 PMU0	MODE1	MODE0	CH3	CH2	CH1	CH0		
		0	0	0	0	0	0	Write to System Control Register					
		0	0	0	1	Select DAC	×	×	×	СНО			
		0	0	1	0	See below		×	×	CH1	×		
		0	0	1	1			×	×	CH1	CH0		
		0	1	0	0			×	CH2	×	×		
		-	-	-	-			-	-	-	-		
		1	0	0	0			CH3	×	×	×		
		-	-	-	-			-	- CH2	- CH1	-		
		1	1	1	0	_		CH3			×		
		1	1	1	1			CH3	CH2	CH1	CH0		
23	MODE1	Mode Bit	s, MODEC	and	MODE1 allow	addressing o	f the DAC gain (m), o	ffset (c )	or input	register (	x1)		
22	MODE0	MODE	1 MOD	E0	Action								
		0	0		System Cont	rol Register o	r PMU Register						
		0	1		DAC Gain (r	n) Register							
		1	0		DAC Offset	(c) Register							
		1	1		DAC Input [	Data Register	, (x1)						
DAC REGIST	ER SPECIFIC BITS												
21,20,19	A5,A4,A3	DAC Address Bits. A5 to A3 select which register set is addressed. See Table 21											
18,17,16	A2,A1,A0	DAC Address Bits, A2 to A0 select which DAC is addressed. See Table 21											
15 to 0(LSB)	D15 (MSB) to D0(LSB)	16 DAC Data bits. D15 MSB.											

### Table 20. DAC Register Functions

### DAC Addressing

For the FIN and Comparator (CPH & CPL) DACs, there are sets of x1, m and c registers for each current range and for the voltage range, but only two sets for the Clamp function (CLL and CLH).

When calibrating the device, m and c registers allow volatile storage of offset and gain coefficients. Calculation of the corresponding DAC x2 register only occurs when x1 data is loaded (no internal calculation occurs on m or c updates).

There is one Offset DAC per all four channels in the device, it is addressed through any PMU0-3 address. The Offset DAC only has an input register associated with it; there are no m or c registers for this DAC. When writing to this DAC, set both Mode bits high to address the DAC input register (x1).

This address table is also used for readback of a particular DAC address.

Table 21.	DAC Register	Addressing
I ubic 21.	DITORCERISCO	ridarcoomig

			Address b	oits A5 to A	3 (DAC ADDRESS	5 Register)						
		Register Set	000			001	010	011	100	101	110	111
A2 to A0			MODE1	MODE0								
(REGISTER			0	1	RESERVED							
ADDRESS)			1	0	RESERVED							
	000	±5µA l range	1	1	OFFSET DAC	FIN	RESERVED	RESERVED	CPL	СРН	RESERVED	RESERVED
	001	±20μA l range	RESERVED			FIN	RESERVED	RESERVED	CPL	СРН	RESERVED	RESERVED
	010	±200μA I range	RESERVED			FIN	RESERVED	RESERVED	CPL	СРН	RESERVED	RESERVED
	011	±2mA I range	RESERVED			FIN	RESERVED	RESERVED	CPL	СРН	RESERVED	RESERVED
	100	±external I range	RESERVED			FIN	CLL I <sup>1</sup>	CLH I <sup>1</sup>	CPL	СРН	RESERVED	RESERVED
	101	Voltage range	RESERVED			FIN	CLL V <sup>2</sup>	CLH V <sup>2</sup>	CPL	СРН	RESERVED	RESERVED
	110	RESERVED	RESERVED			RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED
	111	RESERVED	RESERVED			RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED

<sup>1</sup> CLL I = Clamp Level Low Current register. CLH I = Clamp Level High Current Register. When forcing a voltage, current clamps are engaged, so this register set will be loaded to the Clamp DAC.

<sup>2</sup> CLL V = Clamp Level Low Voltage register. CLH V = Clamp Level High Voltage Register. When forcing a current, voltage clamps are engaged, so this register set will be loaded to the Clamp DAC.

## **READ REGISTERS**

Readback of all the registers in the device is possible via the both SPI and LVDS interfaces. In order to readback data from a register, it is first necessary to write a "readback" command to tell the device which register is required to readback. See Table 22 to address the appropriate channel.

c .1

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1 -

m 11 ee n

Table 22. Read Functions of the AD5522											
B28	B27	B26	B25	B24	B23	B22	B21 to B0	SELECTED REGISTER		2	
RD/WR	PMU3	PMU2	PMU1	PMU0	MODE1	MODE0	DATA BITS	CH3	CH2	CH1	CH0
READ FU	INCTION	S				•					
1	0	0	0	0	0	0	All zeros	Read from	m System (	Control Reg	gister
1	0	0	0	0	0	1	All zeros	Read from	n Compara	ator Status	Registers
1	0	0	0	0	1	0	Х	Reserved			
1	0	0	0	0	1	1	All zeros	Read from Alarm Status Register		ter	
<b>READ AI</b>	READ ADDRESSED PMU REGISTER – ONLY ONE PMU REGISTER CAN BE READ AT ONE TIME										
1	0	0	0	1	0	0	All zeros	×	×	×	CH0
1	0	0	1	0	0	0		×	×	CH1	×
1	0	1	0	0	0	0		×	CH2	×	×
1	1	0	0	0	0	0		CH3	×	×	×
<b>READ AI</b>	DDRESSE	D DAC "I	n" Regist	ter – ONI	Y ONE DA	C REGISTE	R CAN BE READ A	T ONE TIM	ΛE		
1	0	0	0	1	0	1	DAC ADDRESS	×	×	×	CH0
1	0	0	1	0	0	1	SEE Table 21	×	×	CH1	×
1	0	1	0	0	0	1		×	CH2	×	×
1	1	0	0	0	0	1		CH3	×	×	×
READ AI	DDRESSE	D DAC "e	:" Registe	er – ONLY	' ONE DAC	REGISTER	CAN BE READ AT	<b>ONE TIM</b>	E		
1	0	0	0	1	1	0	DAC ADDRESS	×	×	×	CH0
1	0	0	1	0	1	0	SEE Table 21	×	×	CH1	×
1	0	1	0	0	1	0		×	CH2	×	×
1	1	0	0	0	1	0		CH3	×	×	×
<b>READ AI</b>	DDRESSE	D DAC "	c1" Regis	ter – ONI	Y ONE DA	C REGISTE	R CAN BE READ A	T ONE TIM	ΛE		
1	0	0	0	1	1	1	DAC ADDRESS	×	×	×	CH0
1	0	0	1	0	1	1	SEE Table 21	×	×	CH1	×
1	0	1	0	0	1	1		×	CH2	×	×
1	1	0	0	0	1	1		CH3	×	×	×

Once the required channel has been addressed, the device will load the 24 bit Readback data into the MSB positions of the 29 Bit serial shift register, the five LSB bits will be filled with zeros. SCLK rising edges clock this readback data out on SDO(framed by the SYNC signal).

A minimum of 24 clock rising edges are required to shift the readback data out of the shift register. If writing a 24-bit word to shift data out of the device, user must ensure that the 24 bit write is effectively a NOP (No Operation) command. The last 5 bits in the shift register will always be 00000b, these five bits will become the MSBs of the shift register when the 24 bit write is loaded. To ensure the device receives a NOP command as outlined in Table 14, the recommended flush command is 0xFFFFFF and no change will be made to any register within the device.

Readback data may also be shifted out by writing another 29 bit write or read command. If writing a 29-bit command, the readback data will be MSB data available on SDO, followed by 00000b.

## **READBACK OF SYSTEM CONTROL REGISTER**

The readback function is a 24 bit word, mode, address and System Control Register data bits as shown in the following table.

#### Table 23. Readback System Control Register Data

Bit	Bit name	Description				
23 (MSB)	MODE1	0				
22	MODE0	0				
SYSTEM C	CONTROL REGISTER SPECI	FIC READBACK BITS				
21	CL3	Readback the status of the individual Clamp Enable bits. A "0" means the clamp is disabled, while a "1" enabled.				
20	CL2	The clamp enable function is also available in the System Control Register. This dual functionality allows flexible				
19	CL1	enable or disabling of this function. When reading back information on the status of the clamp enable function, what was most recently written to the clamp register from either System Control register or PMU register will be				
18	CL0	available in the readback word.				
17	CPOLH3	Readback information on the Comparator Output Enable status. A "1" signifies the function is enabled, while a				
16	CPOLH2	"0" disabled. A logic high indicates that the PMU comparator output is enabled, while if low, it's disabled. The				
15	CPOLH1	comparator output enable function is also available in the PMU Register. This dual functionality allows flexible enable or disabling of this function. When reading back information on the status of the comparator output				
14	CPOLHO	enable of disability of this function, when reading back monitation on the states of the comparator output enable function, what was most recently written to the comparator register from either System Control register or PMU register will be available in the readback word.				
13	CPBIASEN	This readback bit tells the status of the Comparator Enable function. A "1" in this bit position means the Comparator functions are enabled, while a "0" disabled.				
12	DUTGND/CH	DUTGND per channel enable. If this bit is set at "1", DUTGND per channel is enabled, while if "0", individual guard inputs are available per channel.				
11	GUARD ALM	These bits give status on which of these alarm bits trigger the CGALM pin.				
10	CLAMP ALM					
9	INT10K	If this bit is set high, the internal 10k resistor is connected between FOH and MEASVH, and between DUTGND and AGND. If low, they are disconnected.				
8	GUARD EN	Readback status of the Guard amplifies. If high, Amplifiers are enabled.				
7	GAIN1	Status of the selected MEASOUT Output Range.				
6	GAIN0					
5	TMP ENABLE	Information is available on the status of the setting for Thermal shutdown function. Refer to System control				
4	TMP1	write register.				
3	TMP0					
2	LATCHED	This bit tells of the status of the open drain outputs. When high, the open drain alarm outputs are latched outputs, while if low, they are unlatched.				
1 0 (LSB)	Unused Readback bits	Will be loaded with zeros.				

## **READBACK OF PMU REGISTER**

The PMU readback function is a 24 bit word, mode, address and PMU data bits.

Bit	Bit name	Description		
23 (MSB)	MODE1	0		
22	MODE0	0		
PMU REGISTER S	PECIFIC BITS			
21	CH EN	Channel Enable, If high selected channel is enabled, otherwise disabled.		
20	FORCE1	These bits tell what force and measure mode the selected channel is in.		
19	FORCE0			
18	RESERVED	0		
17	C2	These three bits tell what forced or measured current range is set for the selected channel.		
16	C1			
15	CO			
14	MEAS1	Bits MEAS1 and MEAS0 tell which measure mode is selected, voltage, current, temperature sensor or Hi-		
13	MEAS0	Z.		
12	FIN	This bit shows the status of the Force input amplifier.		
11	SFO	The system force and sense lines may be connected to any of the four PMU channels. Reading back the bits tell if they are switched in or not.		
10	SSO			
9	CL	A logic high in this readback position tells if the Per PMU clamp is enabled, while if low, the clamp is disabled. The clamp enable function is also available in the System Control Register. This dual functionality allows flexible enable or disabling of this function. When reading back information on th status of the clamp enable function, what was most recently written to the clamp register from either System Control register or PMU register will be available in the readback word.		
8	CPOLH	A logic high indicates that the PMU comparator output is enabled, while if low, it's disabled. The comparator output enable function is also available in the System Control Register. This dual functionality allows flexible enable or disabling of this function. When reading back information on the status of the comparator output enable function, what was most recently written to the comparator register from either System Control register or PMU register will be available in the readback word.		
7	COMPARE V/I	A logic high selects indicates the selected channel is comparing voltage function, while logic low, current function.		
6	LTMPALM	TMPALM corresponds to the open drain TMPALM output pin which flags the user of a temperature event		
5	TMPALM	exceeding the default or user programmed level. The temperature alarm is a per device alarm, and latched (LTMPALM) and unlatched (TMPALM) bits tell a temperature event occurred and if the alarm still exists (if the junction temperature still exceede the argummed alarm level). To reset an alarm event the user		
		the junction temperature still exceeds the programmed alarm level). To reset an alarm event, the user must write to the CLEAR bit in the PMU register.		
4, 3, 2, 1, 0 (LSB)	Unused Readback bits	Will be loaded with zeros.		

#### **READBACK OF COMPARATOR STATUS REGISTER**

The Comparator output status Register is a read only register giving access to the output status of each of the comparators on the chip. Table 25 shows the format of the comparator readback word.

Bit	Bit name	Description
23 (MSB)	MODE1	0
22	MODE0	1
COMPARATOR	STATUS REGISTER SPECIFIC	BITS
21	CPOLO	Comparator output conditions per channel corresponding to the comparator output pins.
20	СРОНО	
19	CP0L1	
18	CP0H1	
17	CP0L2	
16	CP0H2	
15	CP0L3	
14	CP0H3	
13 to 0 (LSB)	Unused Readback bits	Will be loaded with zeros.

#### Table 25. Comparator Status Readback Register

## **READBACK OF ALARM STATUS REGISTER**

The Alarm Status register is a READ only register that gives information on temperature, clamp and guard alarm events. In the event the Guard and Clamp alarm functions are not used, (the alarm function may be switched off in the System Control Register). In this case, the Temperature alarm status is also available in the contents of any of the four PMU readback registers.

Bit	Bit name	Description
23 (MSB)	MODE1	1
22	MODE0	1
ALARM STA	TUS READBACK REGISTER	SPECIFIC BITS
21	LTMPALM	TMPALM corresponds to the open drain TMPALM output pin which flags the user of a temperature event
20	TMPALM	exceeding the default or user programmed level. The temperature alarm is a per device alarm, and latched (LTMPALM) and unlatched (TMPALM) bits tell a temperature event occurred and if the alarm still exists (if the junction temperature still exceeds the programmed alarm level). To reset an alarm event, the user must write to the CLEAR bit in the PMU register.
19	LGO	LGx is the per channel latched Guard Alarm bit and Gx is an unlatched alarm bit. These bits give
18	GO	information on which channel flagged an alarm on the open drain alarm CGALM pin and if the alarm
17	LG1	condition still exists.
16	G1	-
15	LG2	-
14	G2	-
13	LG3	-
12	G3	-
11	LCO	$\overline{LCx}$ is a per channel latched Clamp alarm bit and $\overline{Cx}$ is the unlatched alarm bit. These bits give
10	CO	information on which channel flagged an alarm on the open drain alarm CGALM pin and if the alarm
9	LC1	condition still exists.
8	<u>C1</u>	
7	LC2	
6	<u>C2</u>	
5	LC3	
4	<u>C3</u>	
3 to 0 (LSB)	Unused Readback bits	Will be loaded with zeros.

#### Table 26. Alarm Status Readback Register

#### **READBACK OF DAC REGISTER**

The DAC readback function is a 24 bit word, mode, address and DAC data bits.

#### Table 27. DAC Register Readback

Bit	Bit name	Description		
23 (MSB)	MODE1	0		
22	MODE0	0		
DAC READBACK REGISTER SPECIFIC BITS				
21 to 16	A5, A4, A3, A2, A1	Address Bits indicating the DAC register that is read.		
15 to 0 (LSB)	D15 to D0	Contents of the addressed DAC register (x1, m or c).		

## **POWER ON DEFAULT**

The power on default for all DAC channels is that the contents of each m register is set to full-scale (0xFFFF) and c register to midscale(0x8000). The contents of the DAC registers are :

Offset DAC: 0xA492, FIN DACs: 0x8000, CLL DACs: 0x0000, CLH DACs: 0xFFFF, CPL DACs: 0x0000, CPH DACs: 0xFFFF

The power on default for the Alarm Status Register is 0xFFFFF0, while the Comparator Status registers powers up at 0x400000. The power on defaults of the PMU register and the System Control Register are shown below.

	SYSTEM CONTROL REG	ISTER POWER ON DEFAULT	PMU REGISTER POWER ON DEFAULT		
Bit	Bit name	Description	Bit name	Description	
21 (MSB)	CL3	0	CH EN	0	
20	CL2	0	FORCE1	0	
19	CL1	0	FORCE0	0	
18	CL0	0	RESERVED	0	
17	CPOLH3	0	C2	0	
16	CPOLH2	0	C1	1	
15	CPOLH1	0	C0	1	
14	CPOLH0	0	MEAS1	1	
13	CPBIASEN	0	MEAS0	1	
12	DUTGND/CH	0	FIN	0	
11	GUARD ALM	0	SFO	0	
10	CLAMP ALM	0	SSO	0	
9	INT10K	0	CL	0	
8	GUARD EN	0	CPOLH	0	
7	GAIN1	0	COMPARE V/I	0	
6	GAIN0	0	LTMPALM	1	
5	TMP ENABLE	1	TMPALM	1	
4	TMP1	0	Unused Data Bits	0	
3	TMP0	0		0	
2	LATCHED	0		0	
1	Unused Data Bits	0		0	
0 (LSB)	1	0		0	

#### Table 28. Power on Default for System Control Register and PMU Register

## SETTING UP THE DEVICE ON POWER ON

On power on, default conditions are recalled from the power on reset register ensuring each PMU and DAC channel is powered up to a known condition. To operate the device, the user must:

- 1) Configure the device by writing to the System Control register to set up different functions as required.
- 2) Calibrate out errors and load required calibration values to (Gain) m and (Offset) c registers, and load codes to each DAC input register (x1). Once x1 values are loaded to the individual DACs, the calibration engine calculates the appropriate x2 value and stores it ready for the PMU address to call it.
- 3) Load the required PMU channel with the required force mode, current range etc. Loading the PMU channel configures the switches around the Force Amplifier, Measure function, clamps and comparators and also acts as a load signal for the DACs, loading the DAC register with the appropriate stored x2 value.
- 4) As the voltage and current ranges have individual DAC registers associated with them, each PMU register mode of operation calls a particular x2 register. Hence, only updates (changes to x1 register) to DACs associated with the selected mode of operation are reflected to the output of the PMU. If there is a change to the x1 value associated with a different PMU mode of operation, then this x1 value and it's m and c coefficients are used to calculate a corresponding x2 value which is stored in the correct x2 register, but it does not get loaded to the DAC.

## **CHANGING MODES**

There are different ways of handling a mode change:

- Load any DAC x1 values that are required to change. Remember that x1 registers are available per voltage and current range (for Force Amplifier and Comparator DACs), so you can preload these and may not need to make changes. The calibration engine will calculate the x2 values and store them.
- 2) Now change into the new PMU mode. This will load the new switch conditions in the PMU circuitry and load the DAC register with the stored x2 data.
- or
- 1) Use the Hi-Z V or Hi-Z I mode in the PMU register, this makes the amplifier high impedance.
- 2) Now load any DAC x1 values that need to be loaded. Remember that x1 registers are available per voltage and current range, so you can preload these and may not need to make changes.
- 3) When the Hi-Z (V or I) modes are used, the relevant DAC outputs are automatically updated (FIN, CLL, CLH DACs). For example, when selecting Hi-Z V (Voltage), the FIN Voltage x2 result is loaded, offset and gain corrected, cached and loaded to the FIN DAC. When forcing a voltage, current clamps are engaged, so the CLL I (Current) register can be loaded, gain and offset corrected and loaded to the DAC register. Similarly, for the CLH I register.
- 4) Now change into the new PMU mode (FI/FV). This will load the new switch conditions in the PMU circuitry. As the DAC outputs are already loaded, transients when changing current or voltage mode will be minimized.

## **REQUIRED EXTERNAL COMPONENTS**

The minimum required external components are shown in the block diagram below. Decoupling will be very dependent on the type of supplies used, other decoupling on the board and the noise in the system. It is possible more or less decoupling may be required as a result.

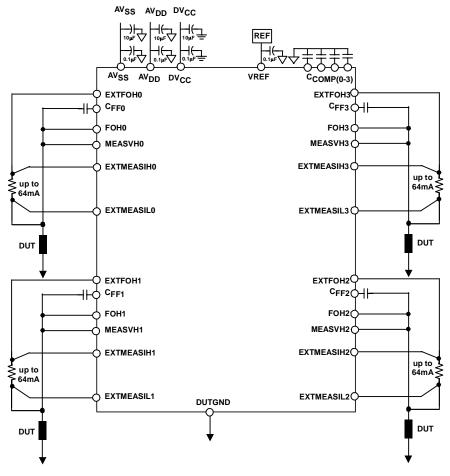


Figure 28. External components required for use with this PMU device.

## POWER SUPPLY DECOUPLING

In any circuit where accuracy is important, careful consideration of the power supply and ground return layout helps to ensure the rated performance. The printed circuit board on which the AD5522 is mounted should be designed so that the analog and digital sections are separated and confined to certain areas of the board. If the AD5522 is in a system where multiple devices require an AGND-to-DGND connection, the connection should be made at one point only. The star ground point should be established as close as possible to the device. For supplies with multiple pins (AVss, AVDD, VCC), it is recommended to tie these pins together and to decouple each supply once.

The AD5522 should have ample supply decoupling of 10  $\mu$ F in parallel with 0.1  $\mu$ F on each supply located as close to the package as possible, ideally right up against the device. The 10 $\mu$ F capacitors are the tantalum bead type. The 0.1  $\mu$ F capacitor should have low effective series resistance (ESR) and effective series inductance (ESI), such as the common ceramic types that provide a low impedance path to ground at high frequencies, to handle transient currents due to internal logic switching.

Digital lines running under the device should be avoided, because these couple noise onto the device. The analog ground plane should be allowed to run under the AD5522 to avoid noise coupling (only with the package with paddle up).. The power supply lines of the AD5522 should use as large a trace as possible to provide low impedance paths and reduce the effects of glitches on the power supply line. Fast switching digital signals should be shielded with digital ground to avoid radiating noise to other parts of the board, and should never be run near the reference inputs. It is essential to minimize noise on all VREF lines. Avoid crossover of digital and analog signals. Traces on opposite sides of the board should run at right angles to each other. This reduces the effects of feedthrough through the board. As is the case for all thin packages, care must be taken to avoid flexing the package and to avoid a point load on the surface of this package during the assembly process.

Also note that the exposed paddle of the AD5522 is connected to the negative supply  $\mathrm{AV}_{\text{SS}}.$ 

## **TYPICAL APPLICATION FOR THE AD5522**

Figure 29 shows the AD5522 as used in an ATE system. This device can used as a per pin parametric unit in order to speed up the rate at which testing can be done.

The central PMU shown in the block diagram is usually a highly accurate PMU, and is shared among a number of pins in the tester. In general, many discrete levels are required in an ATE system for the pin drivers, comparators, clamps, and active loads. DAC devices, such as the AD5379, offer a highly integrated solution for a number of these levels. The AD5379 is a dense 40-channel DAC designed with high channel requirements, such as ATE

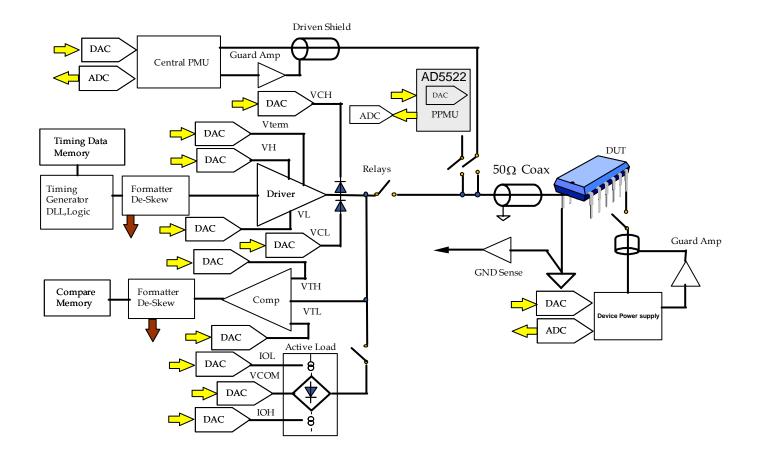


Figure 29. Typical Applications Circuit using the AD5522 as a per pin parametric unit.

## AD5522

#### **OUTLINE DIMENSIONS** 14.20 14.00 SQ 12.20 13.80 1.20 12.00 SQ 0.75 MAX 0.60 0.45 11.80 ЯНАНАНА AAAAAAAAAAAA RARARARARARARARARARAS PIN 1 EXPOSED PAD TOP VIEW (PINS DOWN) 9.50 BSC SQ BOTTOM VIEW 0° MIN 1.05 (PINS UP) 0.20 1.00 20 0.09 20 11 11 0.95 **7**° a 3.5° -►||<del><</del> 0.27 VIEW A 0.50 BSC 0.15 0° SEATING LEAD PITCH 0.08 MAX COPLANARITY 0.05 PLANE 0.22 0.17 VIEW A ROTATED 90° CCW COMPLIANT TO JEDEC STANDARDS MS-026-ADD-HD Figure 30. 80 lead TQFP/EP with exposed pad on bottom 14.20 14.00 SQ 12.20 13.80 12.00 SQ 1.20 0.75 MAX 11.80 0.60 0.45 60 - PIN 1 RABBBBBB EXPOSED PAD 9.50 BSC BOTTOM VIEW (PINS UP) 0° MIN TOP VIEW (PINS DOWN) 1.05 0.20 Ŧ 1.00 0.09 41 0.95 7 3.5° 0.27 VIEW A 6.50 BSC 0.50 BSC 0.15 SEATING PLANE 0° LEAD PITCH 0.08 MAX 0.05 0.22 0.17 **VIEW A ROTATED 90° CCW**

COMPLIANT TO JEDEC STANDARDS MS-026-ADD-HU

Figure 31. 80 lead TQFP/EP with exposed pad on top

### **ORDERING GUIDE**

Model	Function	Package Description <sup>1</sup>	Package Options
AD5522JSVD	Quad PMU with 4 internal current ranges, full comparator function, 1 external current range, SPI and LVDS serial interfaces.	80 Lead TQFP with exposed pad on bottom	SV-80
AD5522JSVUZ <sup>2</sup>	Quad PMU with 4 internal current ranges, full comparator function, 1 external current range, SPI and LVDS serial interfaces.	80 Lead TQFP with exposed pad on top	SV-80
AD5523JCPZ <sup>2,3</sup>	Quad PMU, 4 internal current ranges, window comparator function, SPI interface.	64 Lead LFCSP with exposed pad on bottom 9mm x 9mm	CP-64

 $^{\rm 1}$  Exposed pad is electrically connected internally to AV  $_{\rm SS.}$ 

<sup>2</sup> Lead Free Package.

<sup>3</sup> Reduced functionality. Contact factory for AD5523 datasheet and more details.

# NOTES

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